

Fabrication methods for nanophotonics

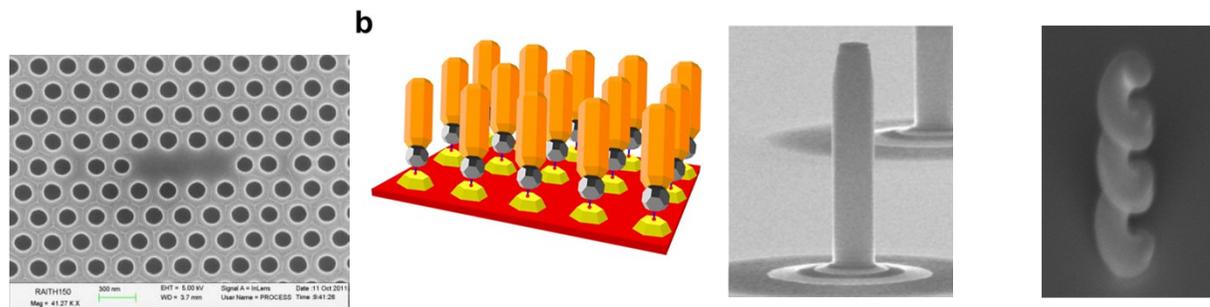
Adriana Passaseo

*CNR-Nanoscienze
National Nanotechnology Laboratories*

- Introduction
- Strategies for Nanofabrication
 - Self assembling method
 - Epitaxial Quantum dot
 - Nanowires
 - Strain driven 3D nanostructures
 - Ion Beam Induced Deposition (IBID) and nanostructuring

Nanophotonics:

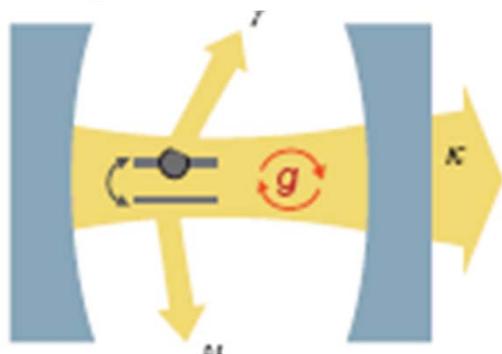
Is defined as the science of light-matter interactions that take place on wavelength and subwavelength scales, where natural or artificial nanostructured material controls the interaction .



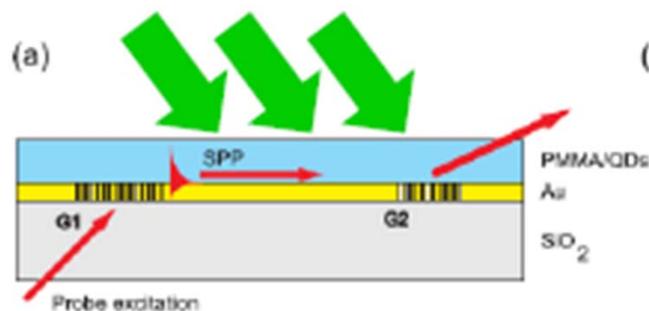
Nanophotonics is where photonics merges with nanoscience and nanotechnology, and where *spatial confinement* considerably modifies light propagation and light-matter interaction.

Nanophotonics devices

Generally they requires tight confinement and low-intensity operation down to the single-photon level. This is achieved fundamentally by two ways: resonant enhancement in dielectric structures where cavity **quantum electrodynamics** (CQED) effects can be exploited , or **plasmonic enhancement** using metals

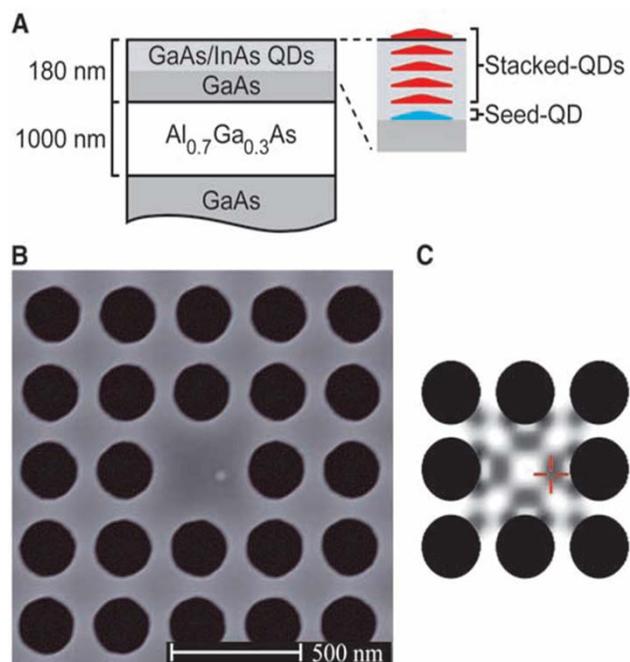


diffraction limited

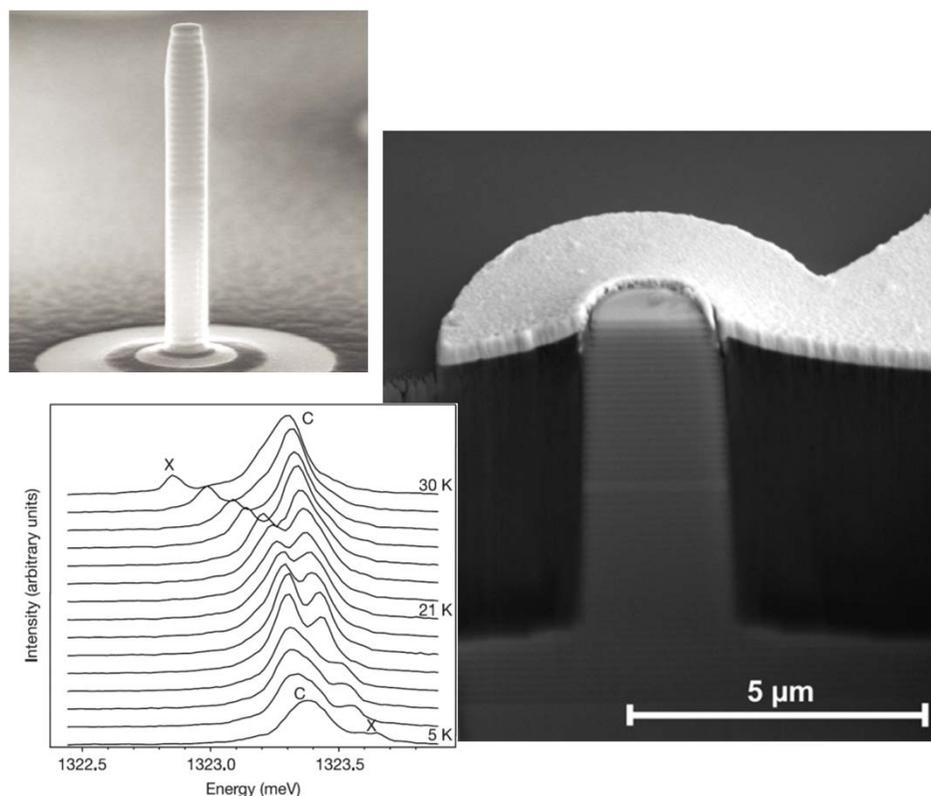


length scales far below the optical wavelength

Single quantum emitter strongly coupled to single cavity modes

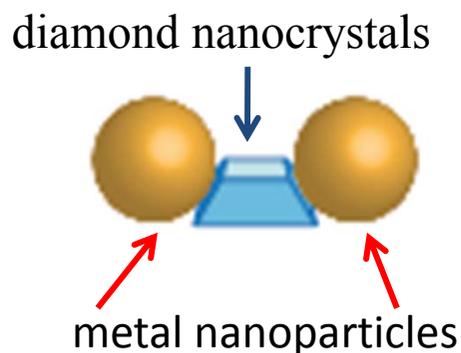


A Badolato et al. *SCIENCE* 2005



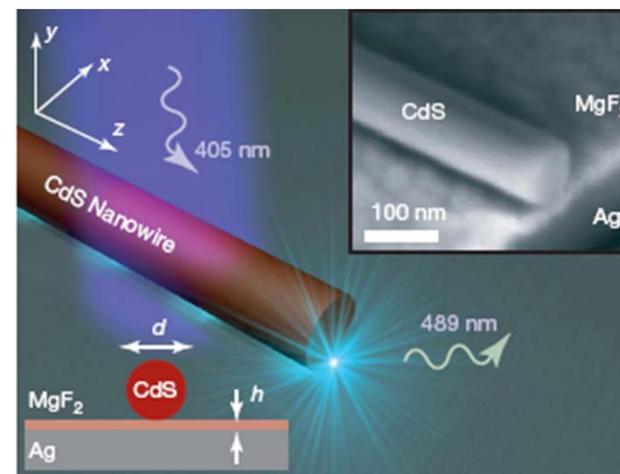
Single quantum emitter coupled to plasmon for field enhancement

Plasmonically enhanced single-photon sources



[Nano Lett. 9, 1694–1698 (2009)].

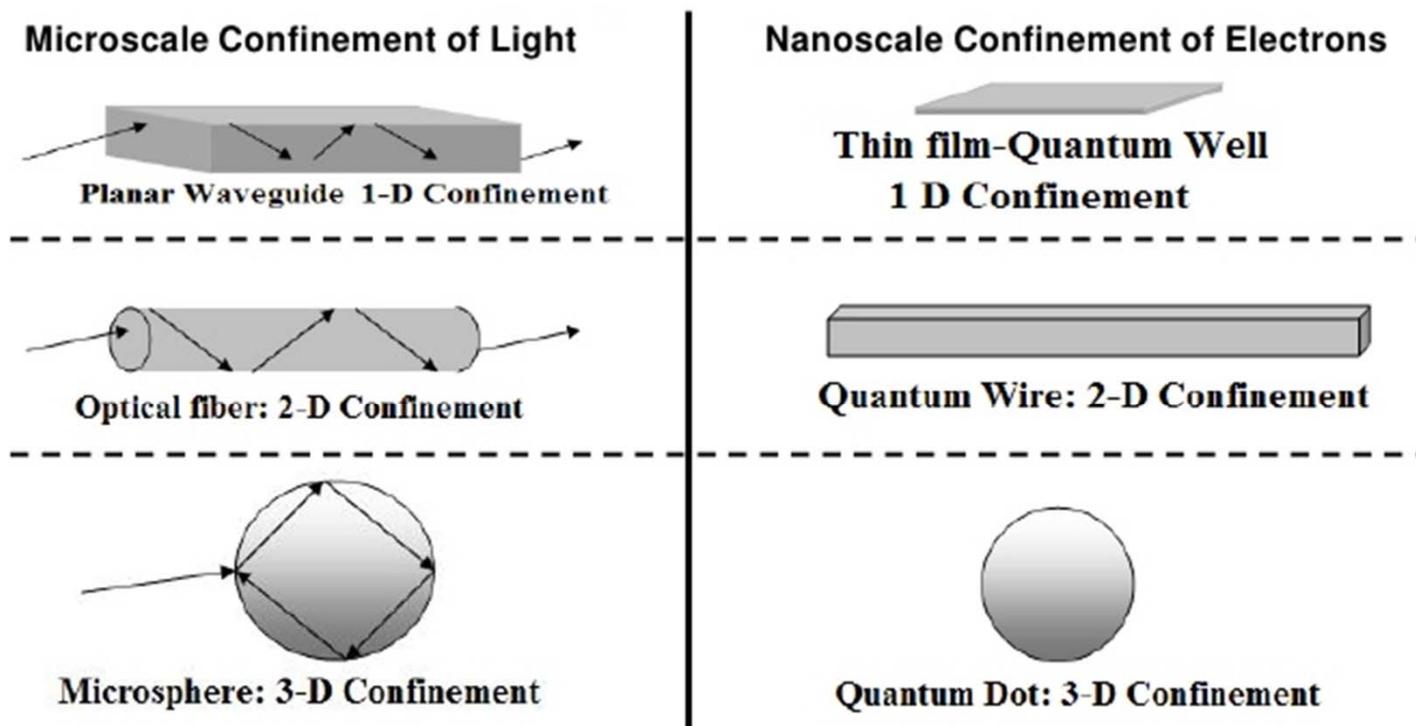
Plasmon lasers



high-gain cadmium sulphide semiconductor nanowire, separated from a silver surface by a 5-nm-thick insulating gap.

[NATURE| Vol 461| 1 October 2009]

The field variations due to the confinement of light is similar to the confinement of electron in a potential well. For light, the confinement is obtained when a region of high refractive index is surrounded by a region with lower refractive index.



Quantum confinement

Size: dimensions must be smaller than the De Broglie Wavelength (λ_{DB}), due to the wave-nature of carriers

Material	Electron effective mass	Hole effective mass
Group IV		
Si (4.2K)	1.08 m_0	0.56 m_0
Ge	0.55 m_0	0.37 m_0
III-V		
GaAs	0.067 m_0	0.45 m_0
InSb	0.013 m_0	0.6 m_0
II-VI		
ZnO	0.19 m_0	1.21 m_0
ZnSe	0.17 m_0	1.44 m_0

$$S \approx \lambda_{DB} = h/m_e v \approx 10\text{nm}$$

Key issue: Scaling down dimensions to their ultimately form

2 different strategies :

Top down approach

Miniaturization obtained by post growth processes (Litographies, etching,...)

Bottom-up approach

**Self assembling
Self ordering**

Self assembling requires interactions between the entities (submicrometre particles, large molecules, atoms) that are strong enough to overcome thermal diffusion,

Strongly depending on material and growth technique

Top-down approach

Confinement obtained by lithography process and etching on QW samples

Resist deposition



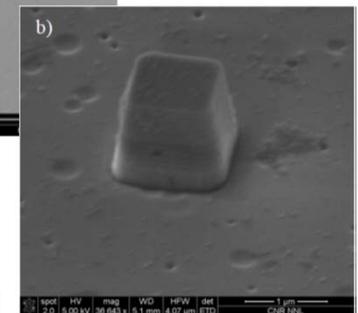
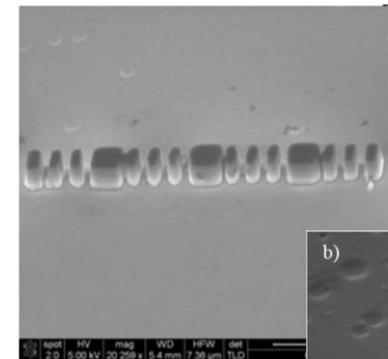
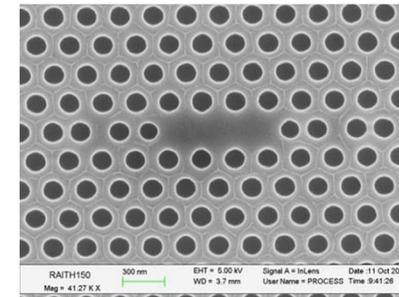
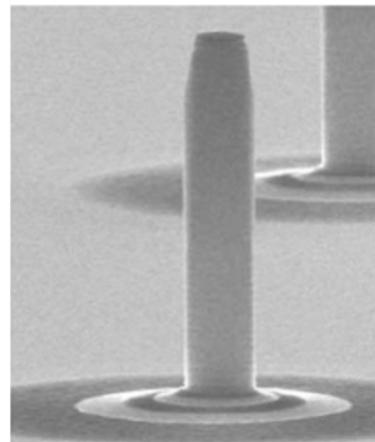
EBL exposure



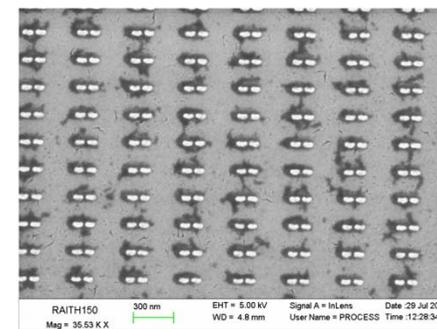
Resist development



Etching



- Defect states at interfaces due to etching

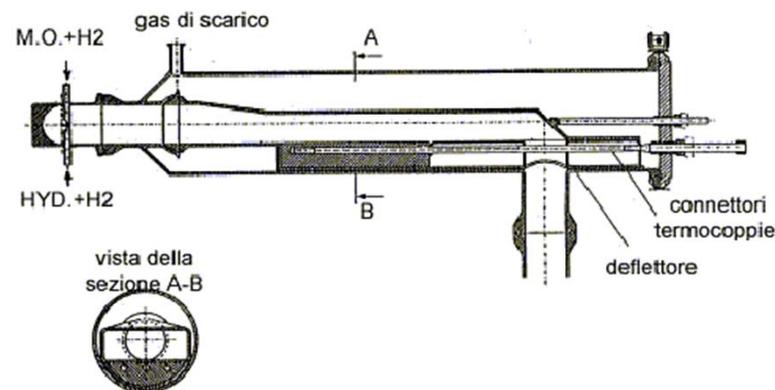


Strongly depending on material and growth technique

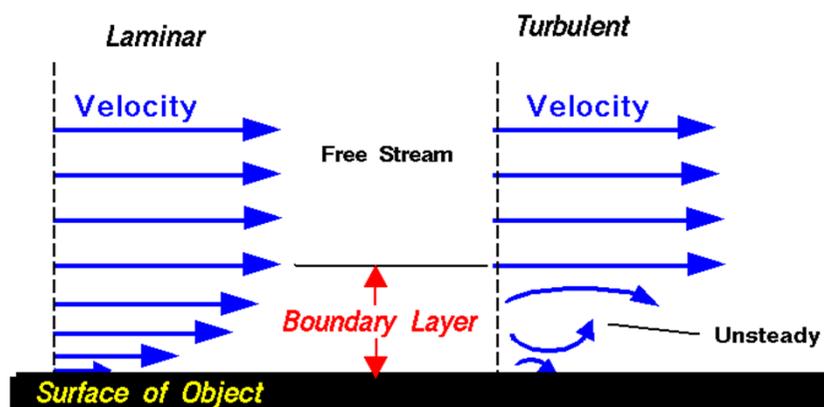
Large choice of growth techniques are available

- Epitaxial techniques (MOCVD, MBE, ALD)
- Sputtering
- PECVD
- Evaporation (thermal or electronic)
- Chemical synthesis
- Self ordering of nanoparticles

MOCVD



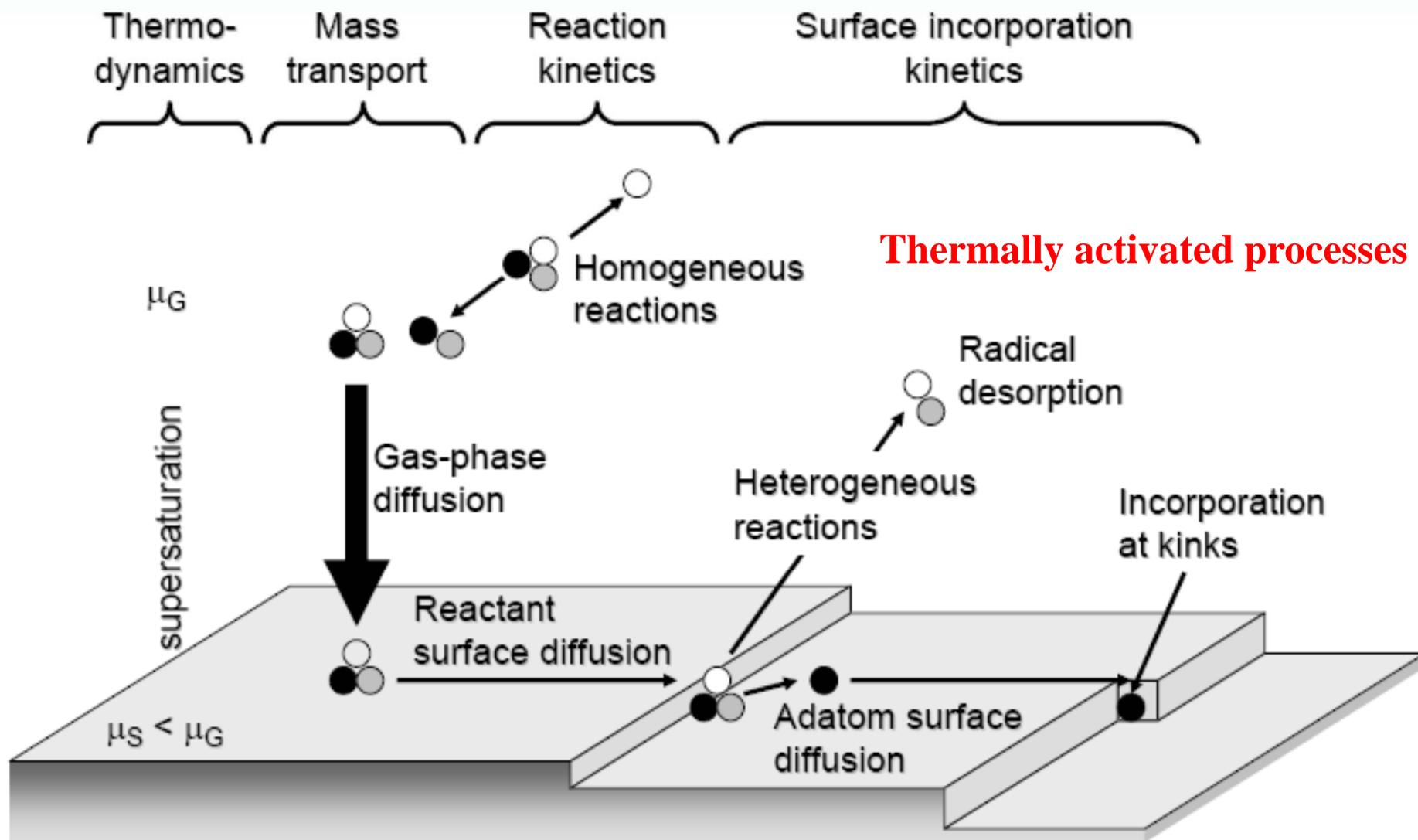
- MO vapor transported by carrier gas
- Hydride group V source gas (toxic)
- Growth controlled by mass transport and surface processes



Velocity is zero at the surface (no-slip)

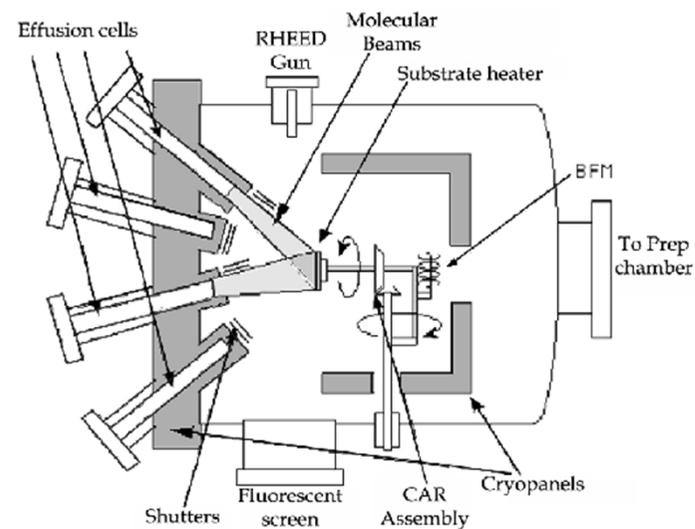
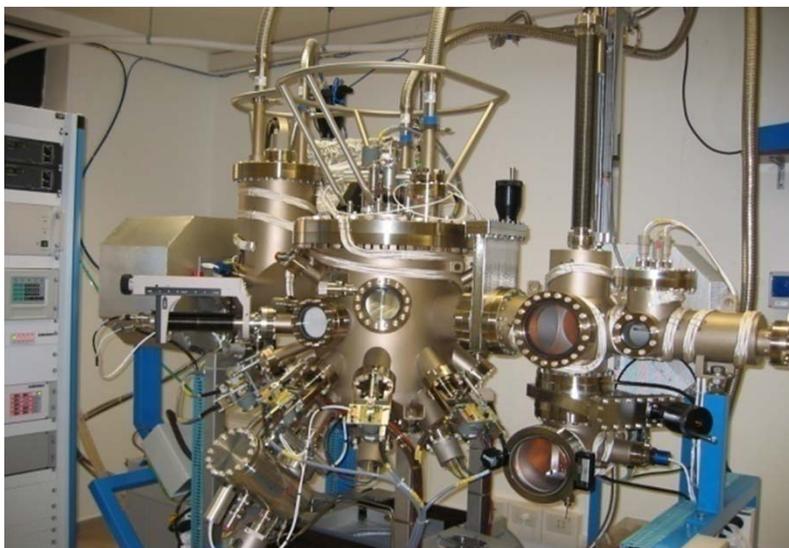
Low vacuum and chemical reactions

Growth step



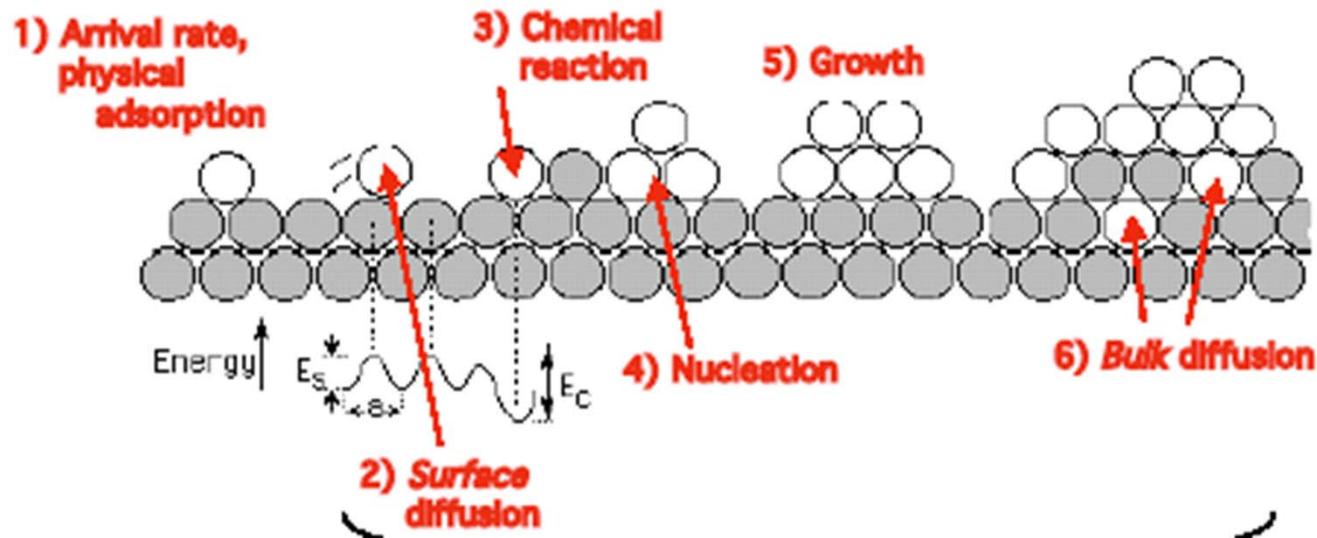
MBE

High controlled evaporation process



- UHV and in situ analysis
- Elemental source material
- No chemical byproducts
- Growth controlled mainly by surface kinetic

$P = 10^{-10}$ torr

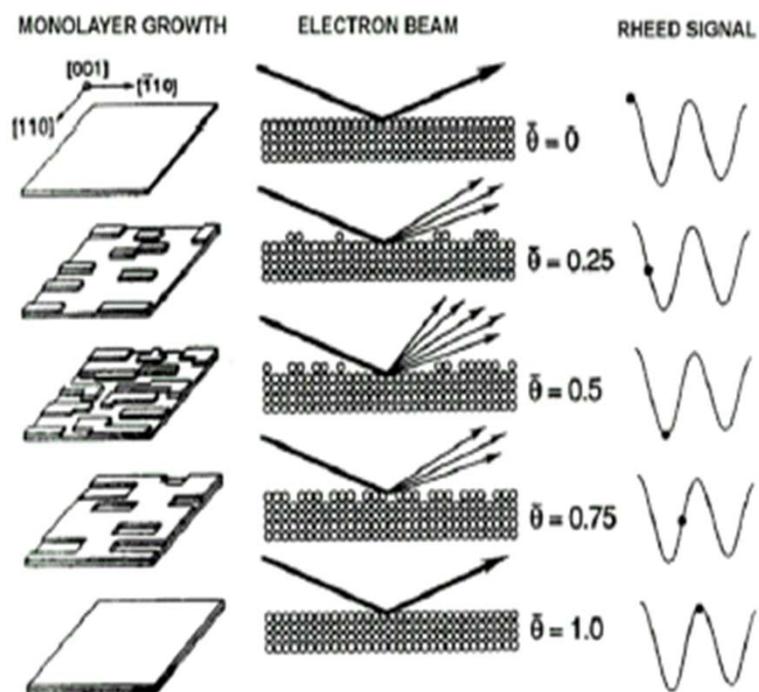


Growth steps:

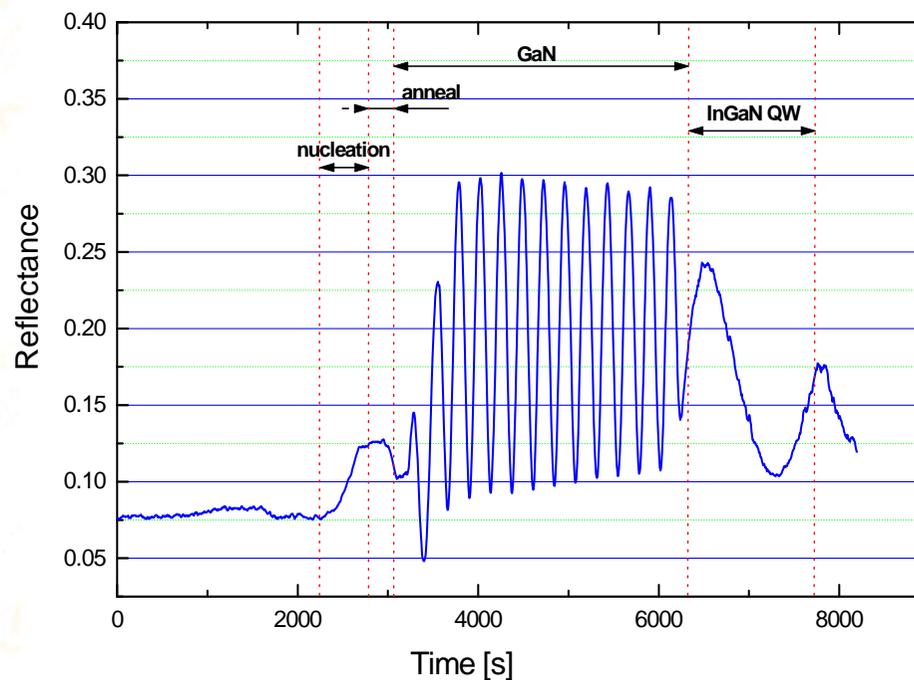
- Adsorption, diffusion and dissociation
- Incorporation on growth site

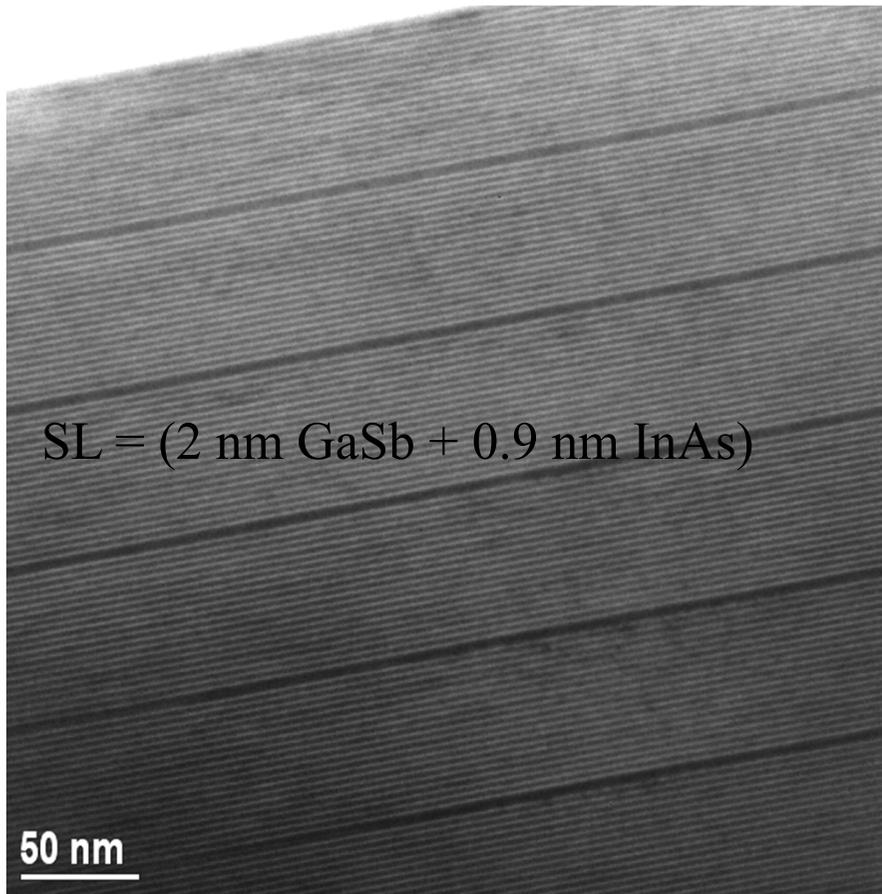
Thermally activated process $E = A \exp(E_a/KT)$

RHEED Measurement (MBE)

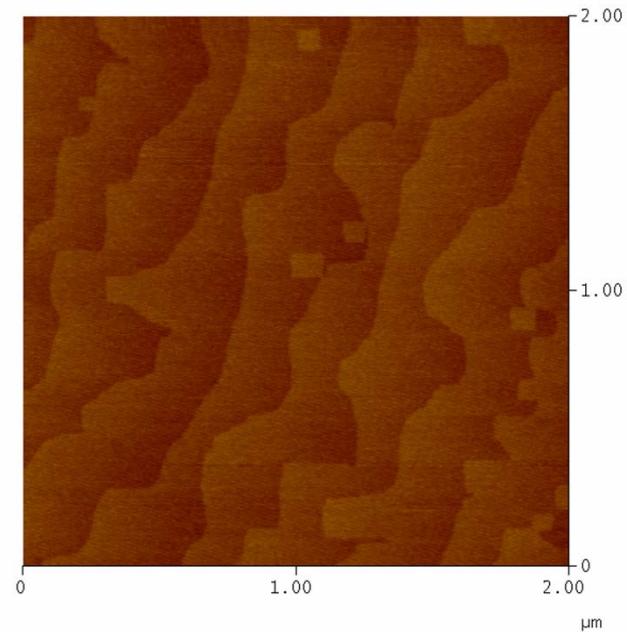


Reflectance Measurement (MOCVD)



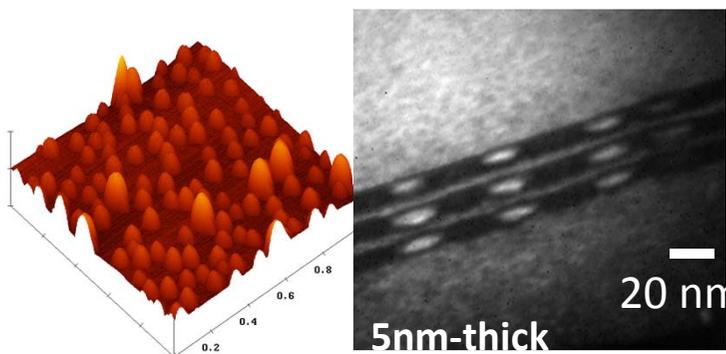


Monolayer control

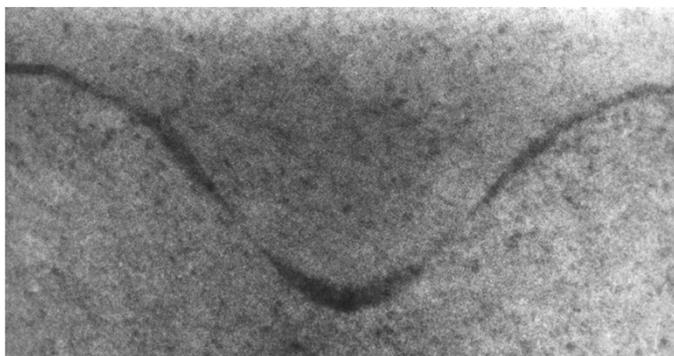


Step-flow growth
mode

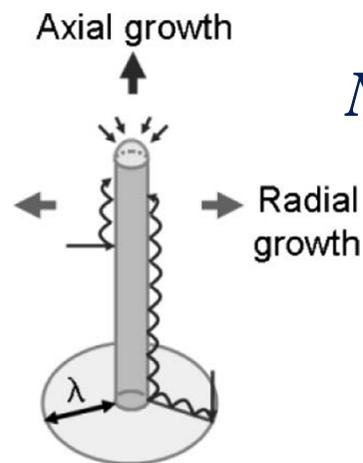
Examples



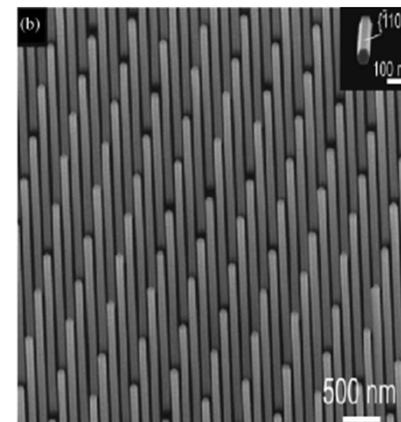
Epitaxial Quantum Dots



V grown quantum-wire



Nanowire

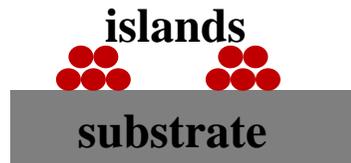
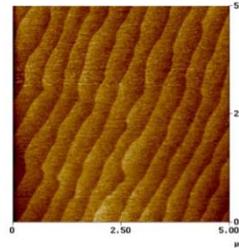
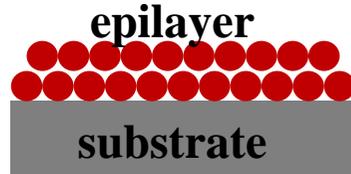


epitaxial growth (Bottom-up approach)

Growth mode

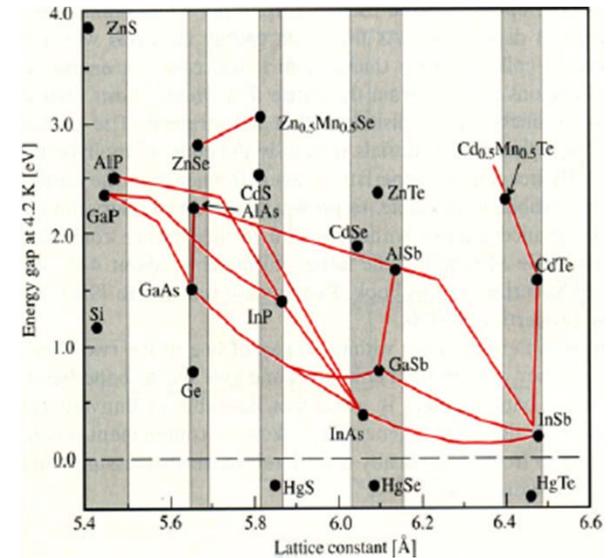
Frank-van der Merwe

(*layer by layer*)



Key parameters:

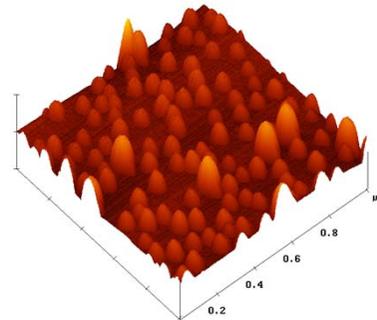
- Strain energy
- Surface energy



Stranski-Krastanov

(*strain-driven*)

Wetting layer



Different material combinations
InAs/GaAs, InAs/InP,
GaSb/GaAs

Stranski-Krastanov growth

$$a_{\text{GaAs}} = 5.65325$$

$$a_{\text{InGaAs}} = 5.8558 \rightarrow f = 4\%$$

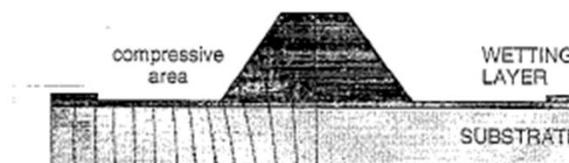
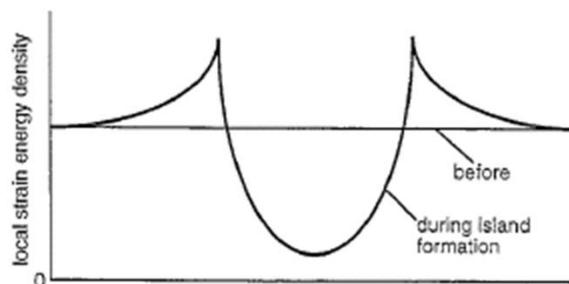
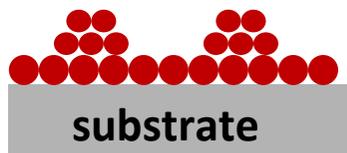
$$\Delta\sigma = \sigma_E + \sigma_I - \sigma_S < 0$$

1° step - Strained 2d Wetting layer

$$E_{el} = Cf^2 At$$



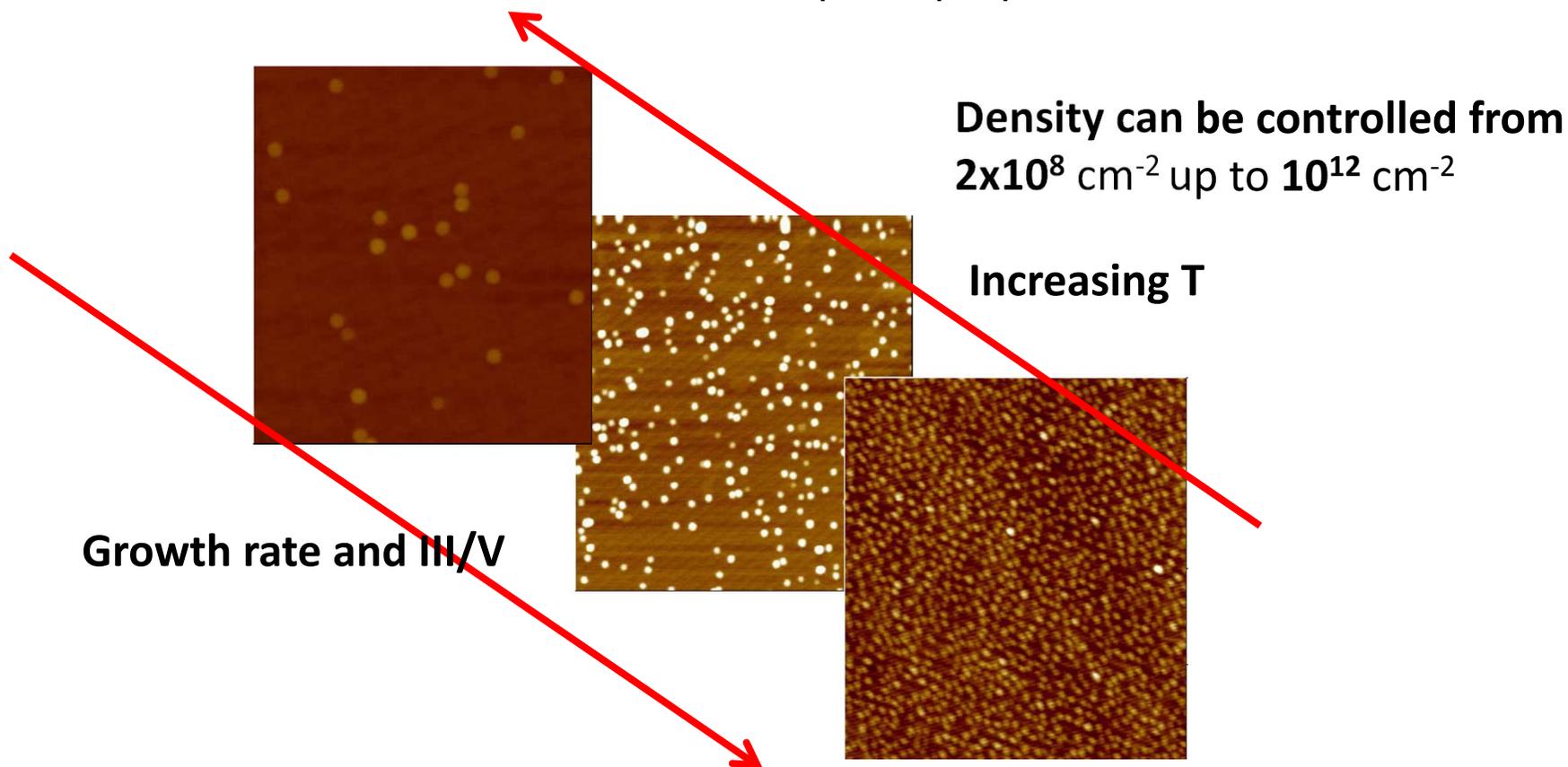
2° step – Nucleation: After a critical thickness strain is relaxed by island formation (reducing deformation energy and increasing surface energy)



- Control of wavelength emission (composition, shape, dimension)
- Uniformity: lateral < 10% and vertical < 5%
- Compositional homogeneity
- Density (10^{10} - 10^{11} dot/cm²)
- Polarization properties

Density control

Strain is the main driving force for the QD formation, but **surface kinetics** is crucial to control the QD structural and optical properties.



[A.Passaseo et al., J. Appl. Phys. 89, 4341 (2001)]

Wavelength control

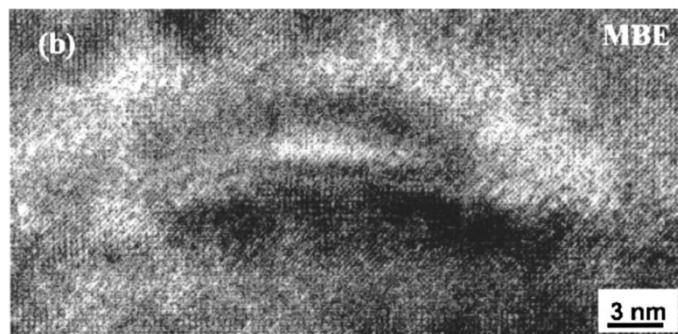
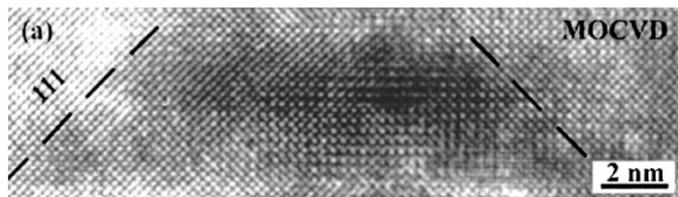
$$E_n = E_g + \frac{\hbar^2 \pi^2}{2m_r L^2}$$

growth dynamics (i.e. growth condition) could controls:

- Size
- Shape
- composition

Principal factor controlling size → **Strain**

Low growth rate, low III/V and temperature can modulate size and aspect ratio



- ← Different shape due to growth technique:
- ✓ Truncated pyramid by MOCVD
 - ✓ Lens shape by MBE

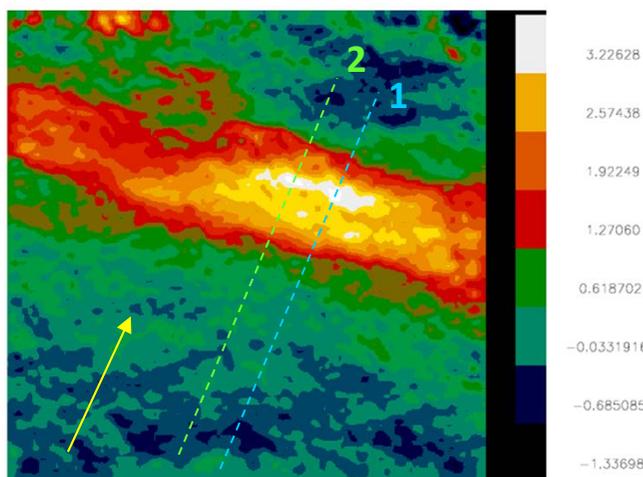
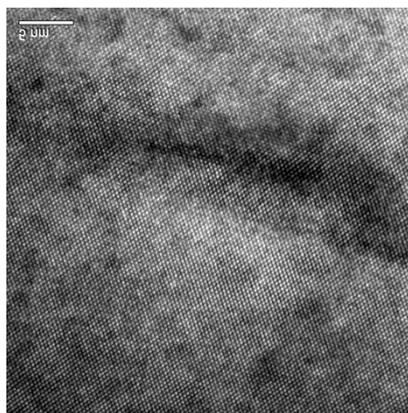
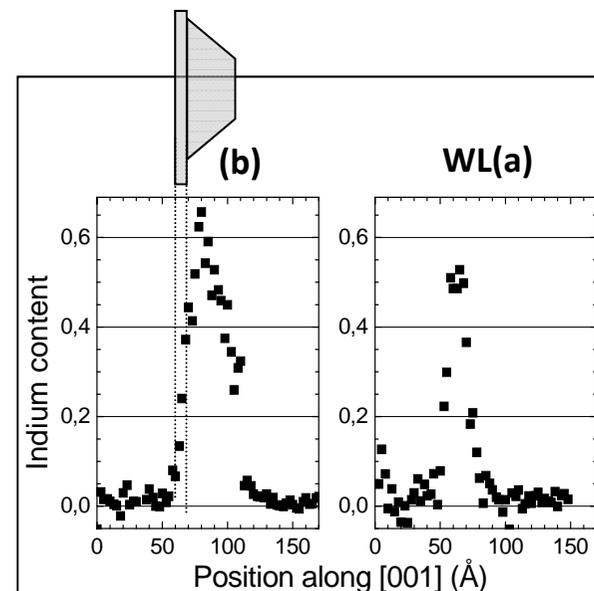
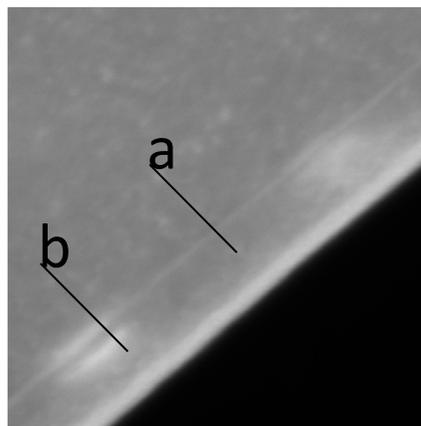
Material composition

Large variation can be found as a function of the growth method and condition (interdiffusion, segregation)

InGaAs QD (50%)
MOCVD

In content enhancement (60 %) at the center of the dots

Weak interdiffusion (about 2-3 MLs)



MBE InAs QD

Maximum In content 80% localized in the upper dot surface

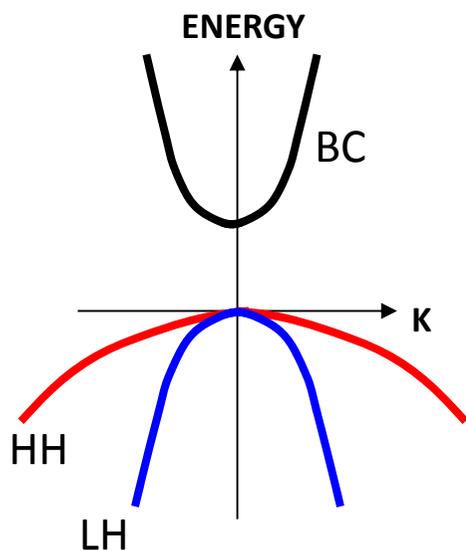
Weak interdiffusion (about 2-3 MLs)

Lattice Distortion Analysis (LADIA)

Polarization properties

Standard SK QDs do emit dominantly in transverse-electric (TE)-mode, due to their flat shape and quasi-biaxial compressive strain.

Bulk material

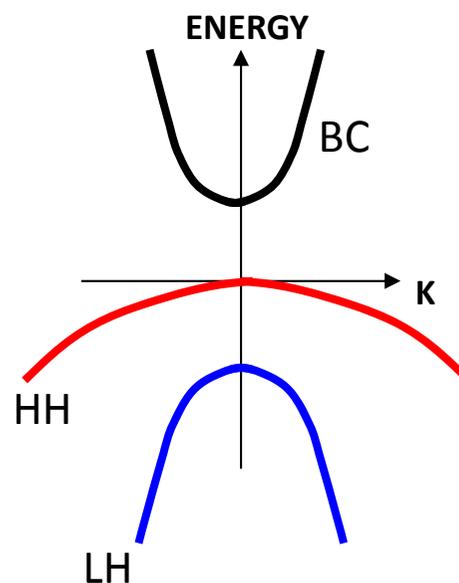


HH and LH degenerate in the valence band



polarization insensitive material
gain

Quantum Dot



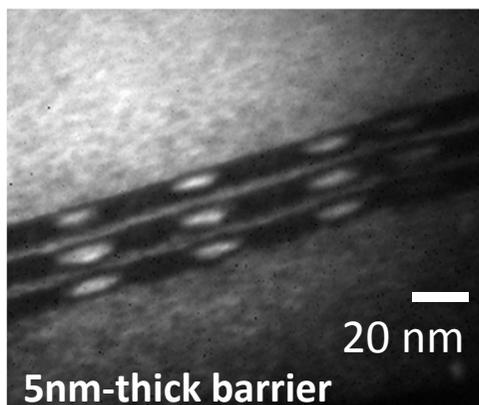
different quantization levels
for HH and LH bands



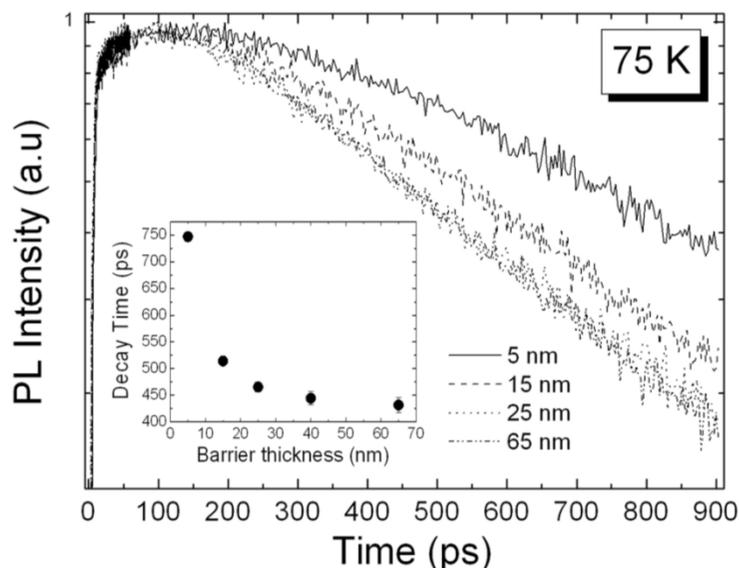
Emission of QD is polarized TE

QDs as an active medium offer potential advantages with regards to polarization because their electronic wavefunctions can be changed by growth.

Electronic coupling of QDs

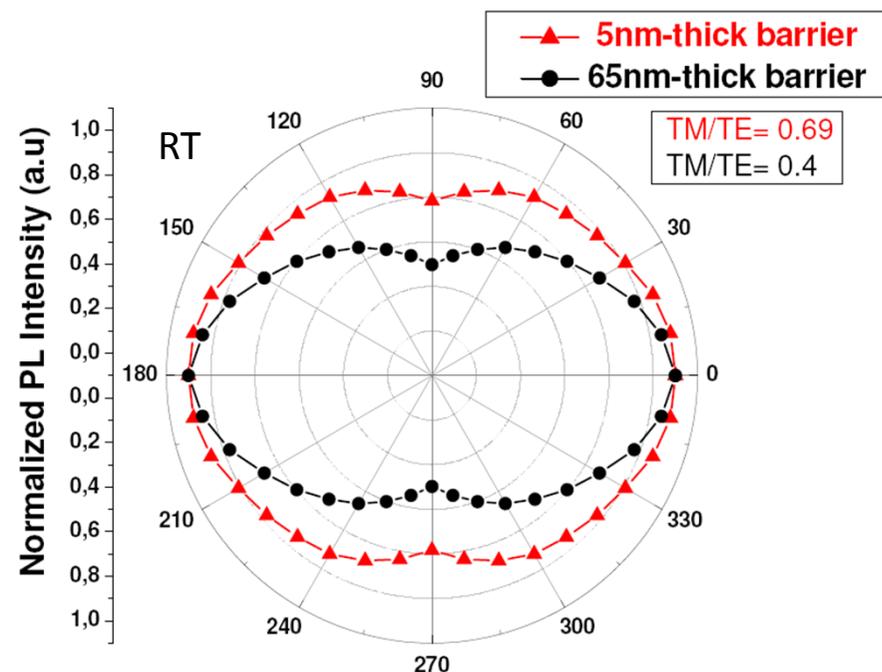


Time resolved measurements



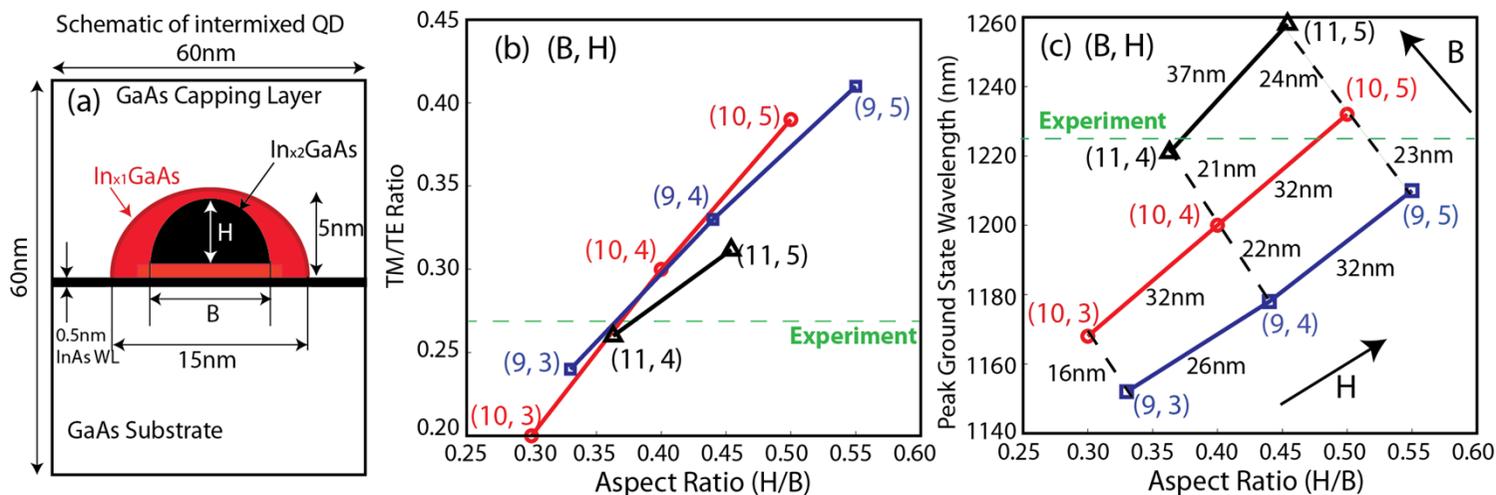
Radiative decay time increase

Polarized PL spectra



TM/TE ratio reaches a value of 0.69 for a sample with 3 QD layers separated by 5nm thick-GaAs spacer

Atomistic simulations

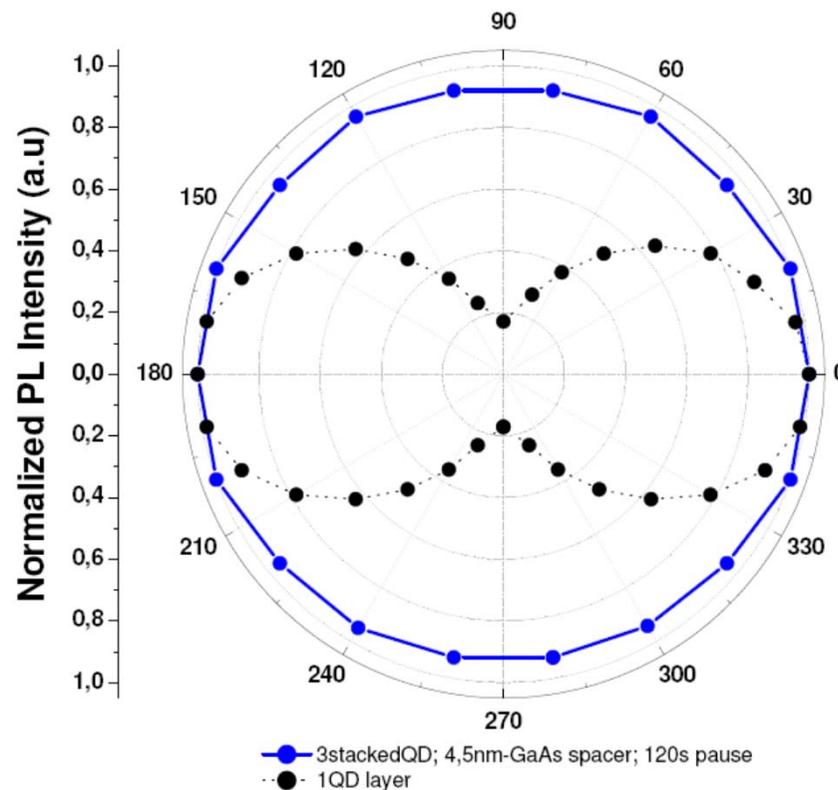
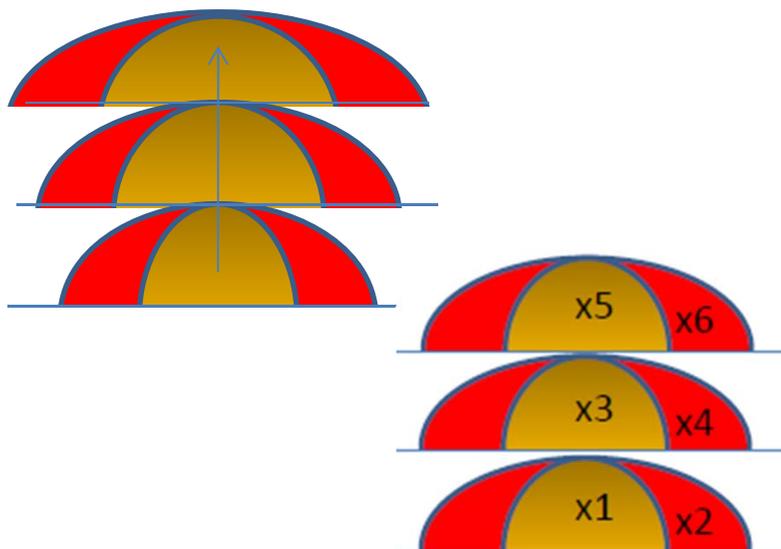


QD Model	ϵ_H	ϵ_B	δE_c meV	δE_{HH} meV	δE_{LH} meV	δE_{HH-LH} meV
(a)	-0.0842	-0.1536	427.7	54	-222.4	278.4
(b)	-0.06	-0.148	304.8	73.2	-193.2	266.4
(c)	-0.0818	-0.1449	415.5	48.6	-212.2	260.8

[M.Usman, Nanotechnology 2012]

Final result

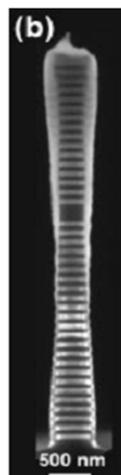
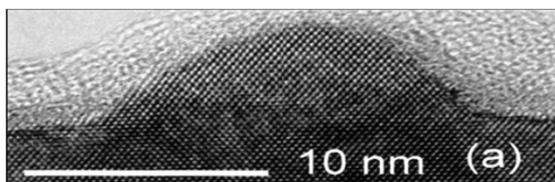
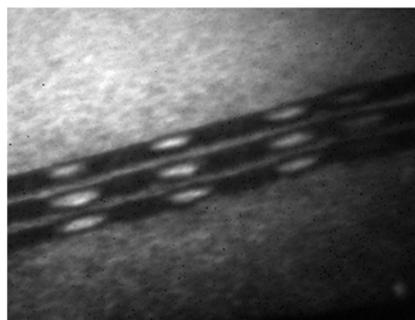
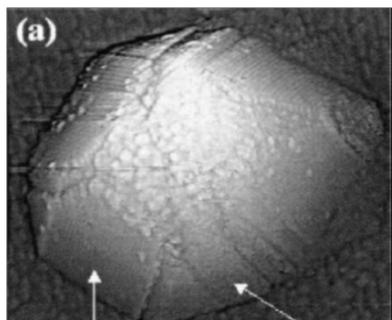
Nearly unpolarized active materials obtained only by playing with surface reconstruction during growth



A nearly total polarization independence (TM/TE=0.92) with only 3 closely QD layers

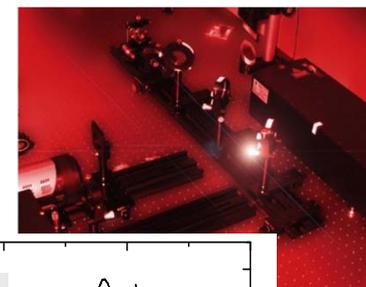
Epitaxial Quantum Dots

Principal application: optoelectronic devices



Devices for optical data transmission:

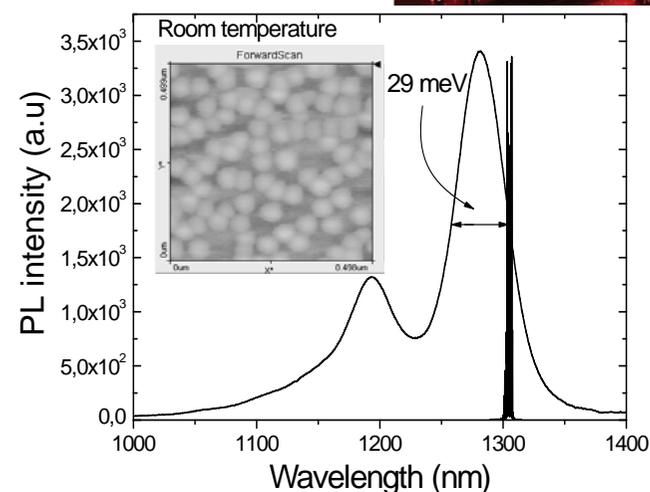
- ✓ Laser sources
- ✓ Semiconductor optical amplifiers (SOAs)
- ✓ Infrared detectors



QD solar cells

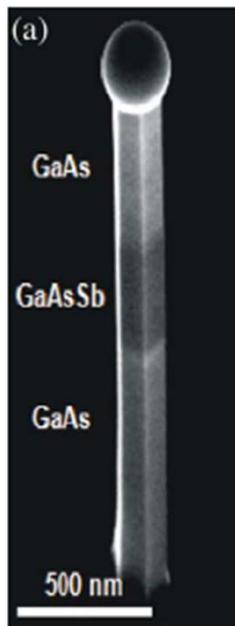
(extended absorption)

Single PHOTON SOURCES for
Quantum Computing/cryptography
(coherent states of charge)



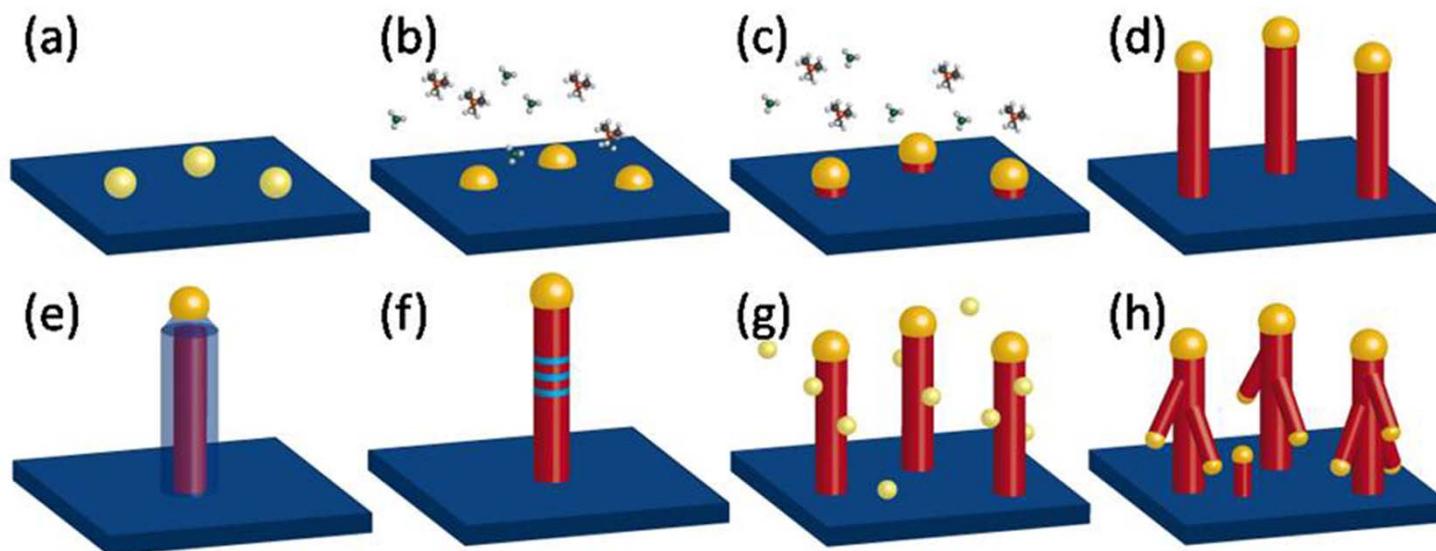
Nanowires

Semiconductor nanowires are filamentary crystals with the diameter being of the order of few nanometers.



The most common method to fabricate nanowires is the vapor–liquid–solid (VLS), in which a metal nanodroplet preferentially gathers and decomposes the growth precursors, allowing the growth of nanowires. The metal most commonly employed for the nucleation and growth is gold

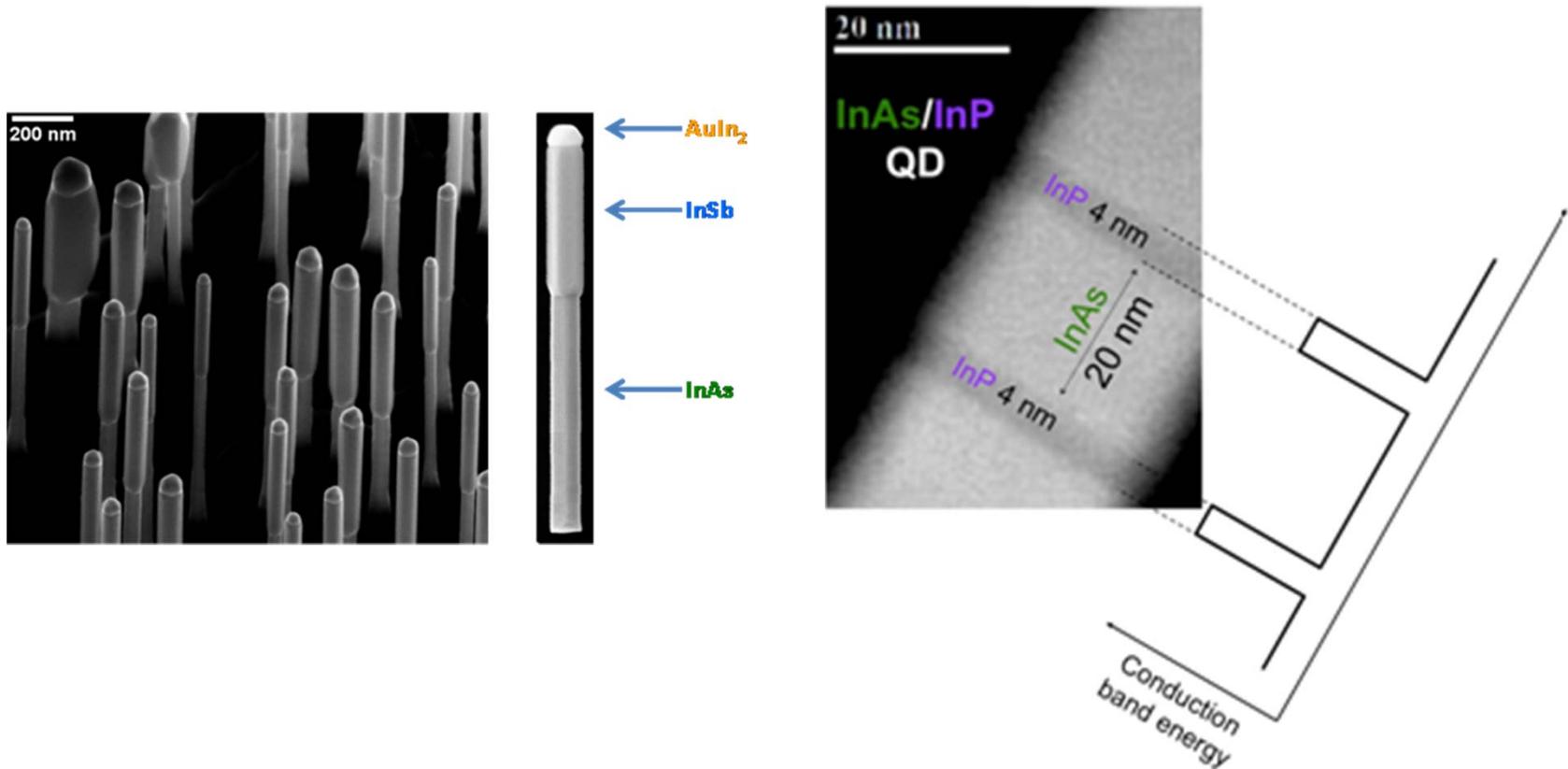
Au assisted growth of GaAs NWs



(a) The seed particles are deposited on the substrate and (b) by heating the substrate to a desired temperature and introducing growth materials an alloy is formed. (c) When a supersaturation of the alloy particle with growth material is achieved, nucleation occurs at the particle-substrate interface. (d) Nanowire growth occurs at the particle-wire interface as long as growth material is provided. (e) By switching to growth conditions favoring planar growth, radial heterostructures, can be grown. (f) Nanowires containing axial heterostructures can be formed by switching between different growth materials. (g) If a second generation of gold particles is deposited onto the as-grown nanowires and (h) the growth process is repeated, branched nanowires for formation of nanowire networks can be grown.

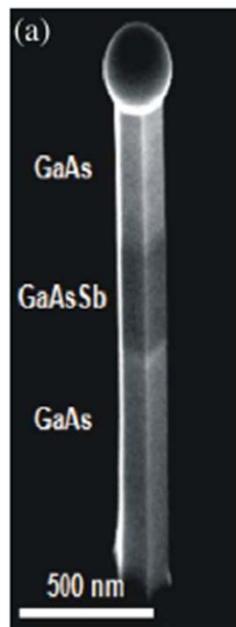
Au assisted growth

InAs-InSb heterostructured nanowires grown by Au-assisted chemical beam epitaxy



L. Lugani et al., J. Cryst. Growth, Vol. 323, Issue 1, 15 (2011), pp. 304-306

Au free nanowire growth

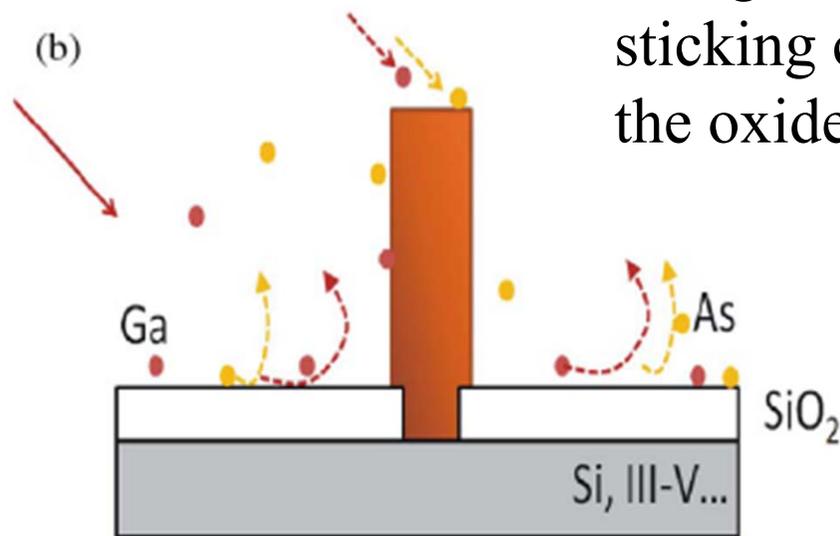


When gold atoms are incorporated in semiconductors, often they form deep level traps and scattering centers

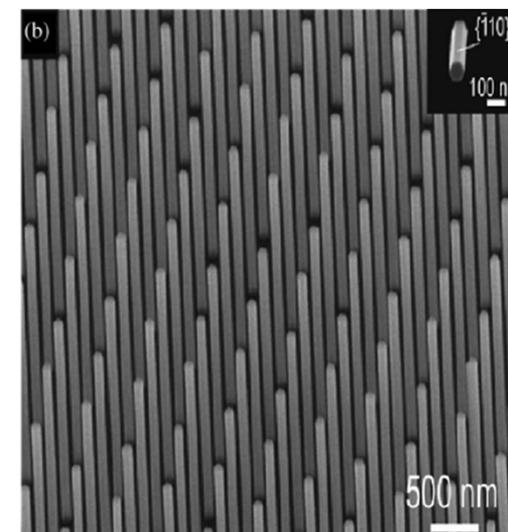
Several strategies have been used to avoid the use of gold for the synthesis of semiconductor nanowires, like **group-III-assisted growth** or **Selective Area Epitaxy (SAE)** on patterned substrate

Selective Area Epitaxy

The growth conditions are chosen so that the sticking coefficient of the adatoms is zero on the oxide and nonzero in the apertures



any substrate orientation can be used.

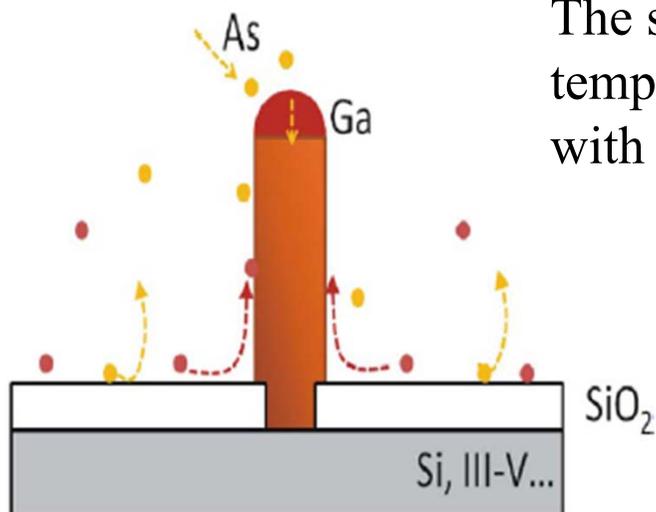


In epitaxy, different facets are formed as a result of the different growth rates between them.

The conditions leading to nanowires correspond to a high growth rate in the $[1\ 1\ 1]_B$ direction and slow in the $\langle 1\ 1\ 0 \rangle$ directions. Nanowires are formed only under high substrate temperatures and low arsine partial pressure (typically $750\ ^\circ\text{C}$ and 5.0×10^{-4} atm.).

the flow of arsenic limits the growth rate.

Ga assisted growth



The substrate temperature must be close to the congruent temperature (gallium liquid droplet can exist in equilibrium with solid)

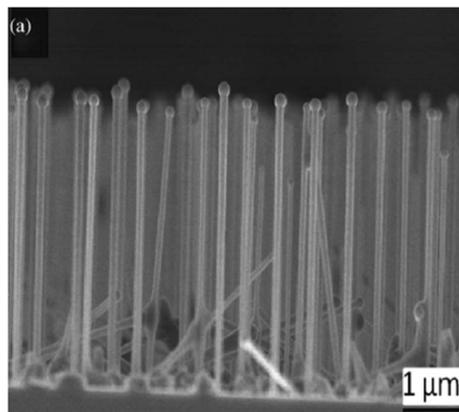
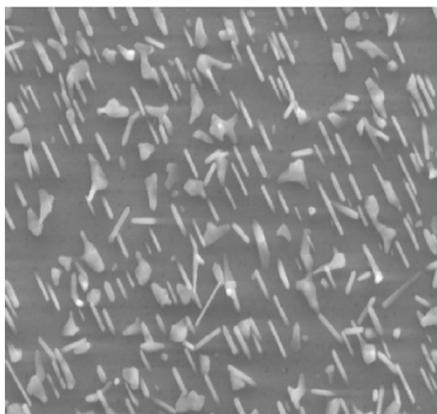


gallium should not wet the surface

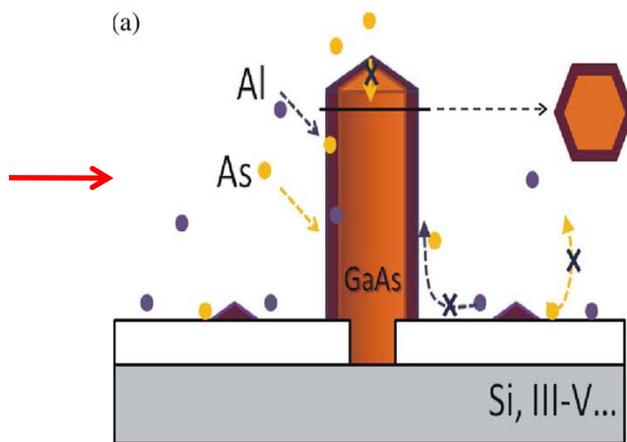
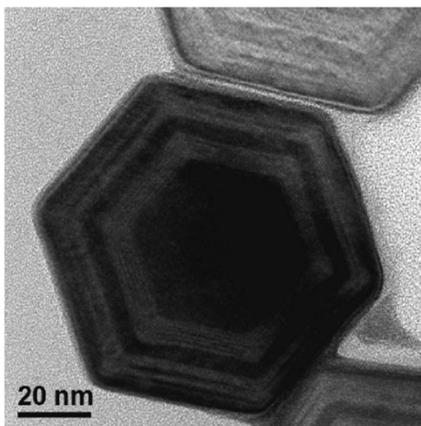
Catalyst-free MBE growth of GaAs NWs under Ga-rich conditions

- 1) As-adatoms impinging on the substrate are immediately desorbed and do not contribute to the growth;
- 2) Ga-adatoms impinging on the substrate diffuse and form droplets, where the NWs nucleate;
- 3) once the NW is formed, Ga-adatoms continue to diffuse through the substrate surface and along the NW facets to continuously refill the Ga droplets;
- 4) As-adatoms impinging on Ga-droplets determine the NW growth rate.

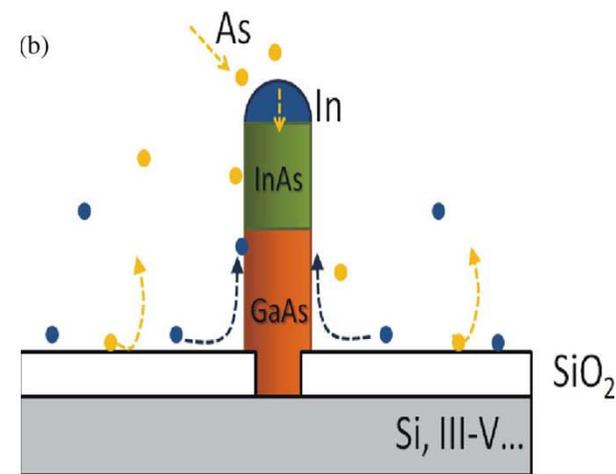
Ga assisted growth



By switching to growth conditions favoring planar growth radial or axial heterostructures can be grown



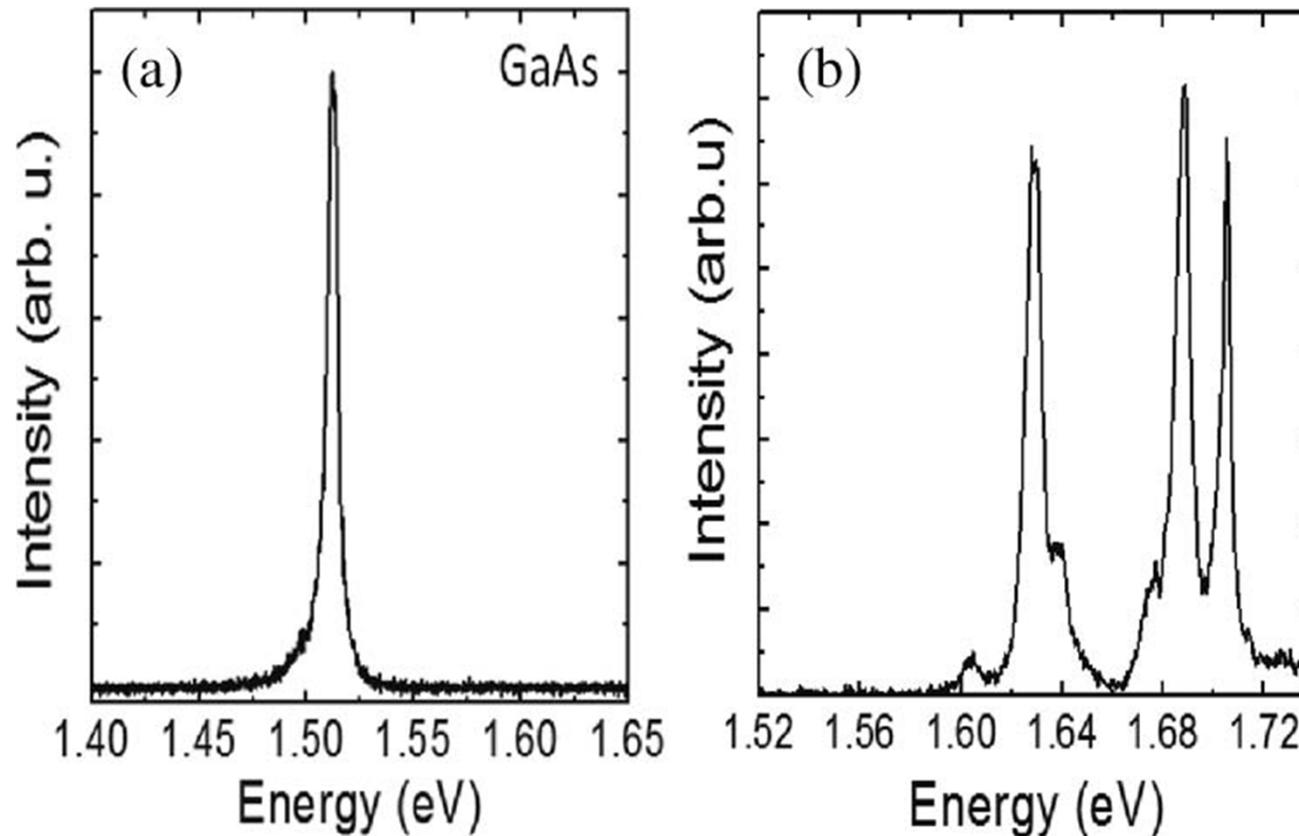
Radial heterostructure



Axial heterostructure

IEEE J. SELECT. TOPICS IN QUANTUM ELECTRONICS, VOL. 17, NO. 4, 2011

Advances on nanophotonics – 52nd Course-Erice, July 2012



(a) PL spectrum of a single GaAs nanowire. (b) PL spectrum of a nanowire containing three prismatic QWs of thicknesses 0.6, 1.4, and 5.8 nm.

[A. Fontcuberta i Morral, *IEEE J. Of Selected Topics in Quantum Electronics*, **17**, 2011]

Advances on nanophotonics – 52nd Course-Erice, July 2012

GaN nanowires

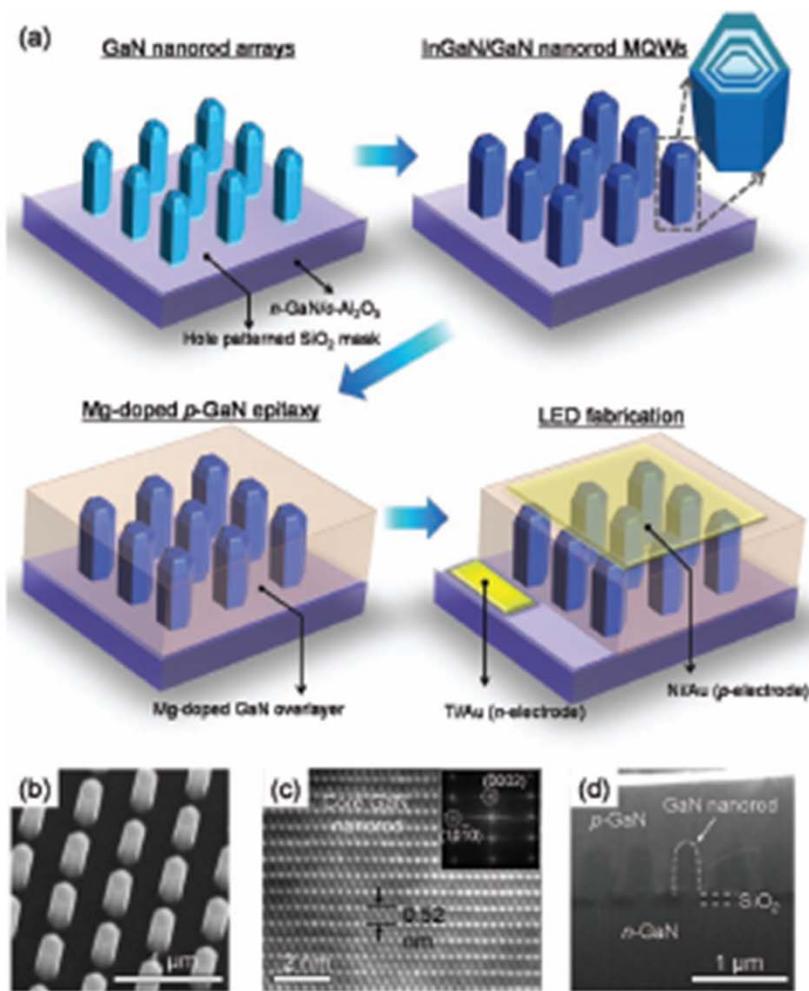


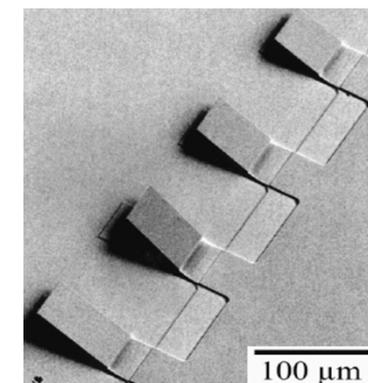
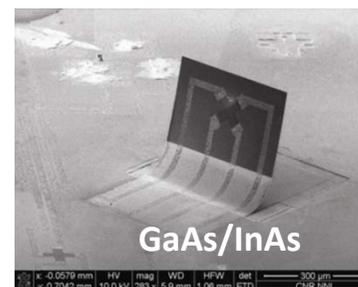
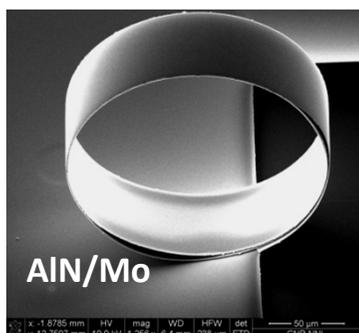
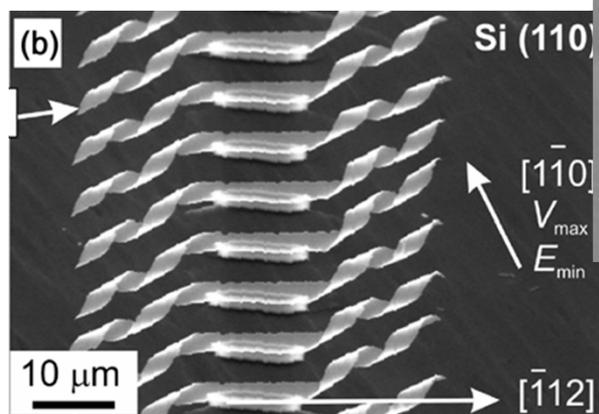
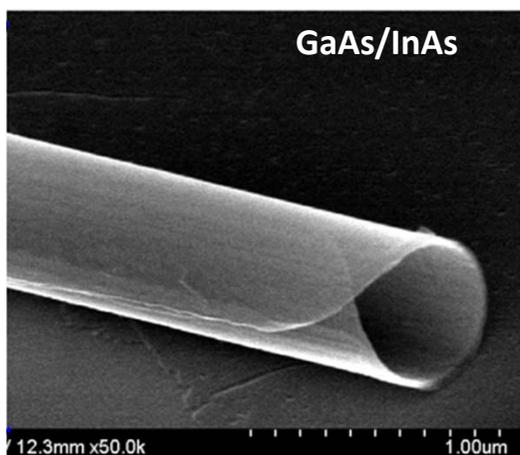
Figure 1. Fabrication of nanorod-embedded LEDs and electron microscopic images. a) Selective MOVPE growth of GaN nanorod arrays on n^+ -GaN/ Al_2O_3 (0001) substrates (left upper panel), followed by heteroepitaxial coating of 3D $\text{In}_x\text{Ga}_{1-x}\text{N}/\text{GaN}$ MQWs (right upper panel). Subsequently, Mg-doped p-GaN was coated on the nanorod MQW arrays to form a continuous overlayer (left bottom panel). The LEDs were fabricated by making ohmic contacts on both the topmost p-GaN surface and n-GaN layer beneath the nanorods (right bottom panel). b) Bird's-eye view SEM image of GaN nanorod arrays. c) HR-TEM image of single-crystalline core n-GaN nanorods. The inset shows the diffraction pattern of the GaN nanorods. d) Cross-sectional SEM image of a Mg-doped GaN overlayer and $\text{In}_x\text{Ga}_{1-x}\text{N}/\text{GaN}$ MQWs on GaN nanorod arrays.

[Advanced Materials Volume 23, Issue 29, 2011](#)

- Introduction
- Strategies for Nanofabrication
 - Self assembling method
 - Epitaxial Quantum dot
 - Nanowires
 - **Strain driven 3D nanostructures**
 - Ion Beam Induced Deposition (IBID) and nanostructuring

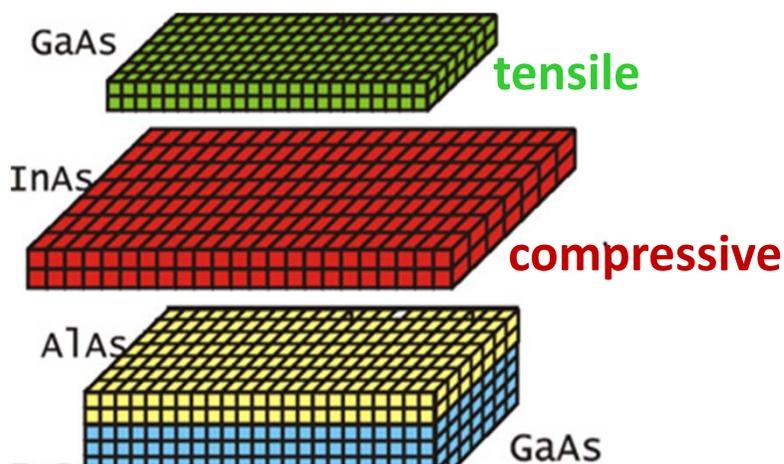
Strain driven 3D nanostructures

3D objects, obtained by strain release, by using a combination of bottom-up and top-down approach

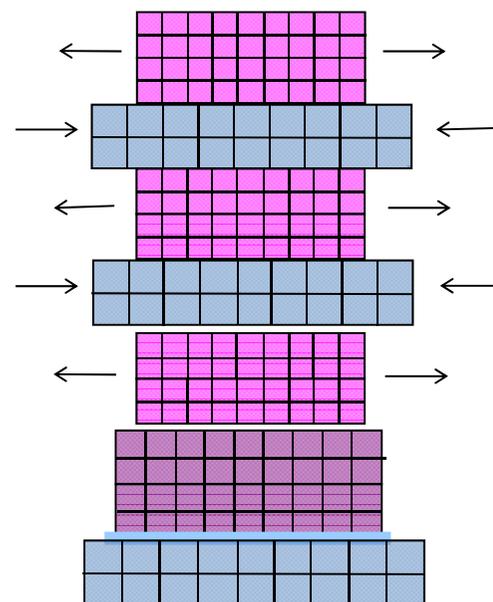


Formation process

bottom-up process: *self-rolling* induced by strain release

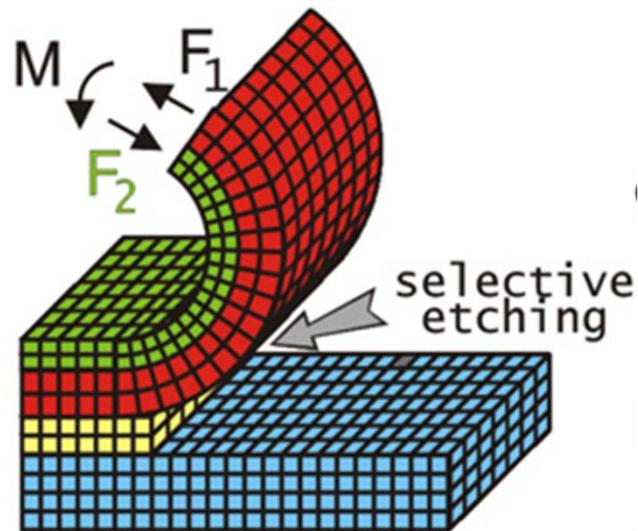


Basic structure: bilayer with opposite strain on sacrificial layer

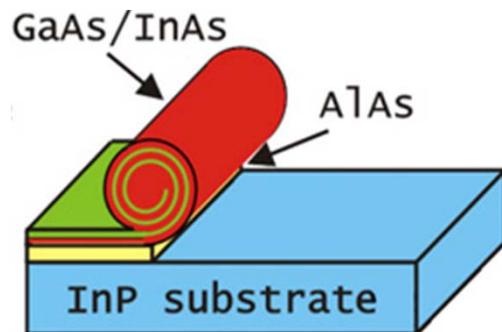


Each layer undergoes opposite elastic forces due to strain

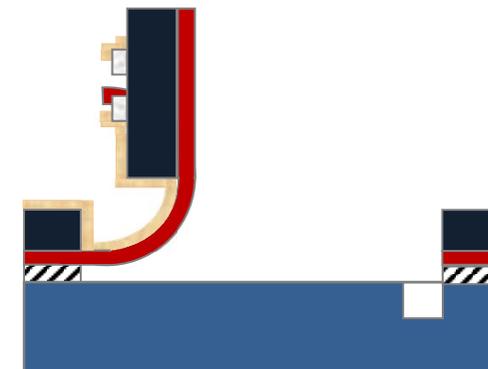
Formation process



By removing the sacrificial layer the bilayer release the strain energy by bending the structure (a momentum M due to the opposite forces F_1 e F_2 is established in the structure)

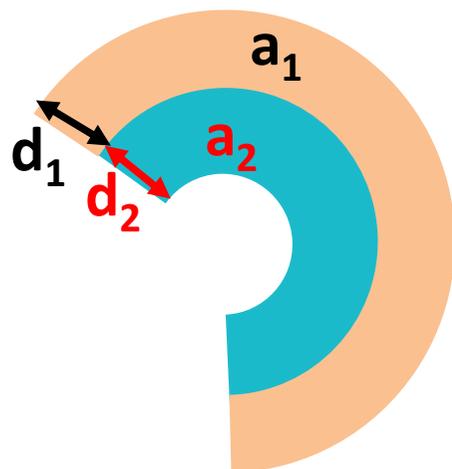


Final shape depend on total stain and etching geometry.



Curvature radius

Depend on built-in strain and bilayer total thickness



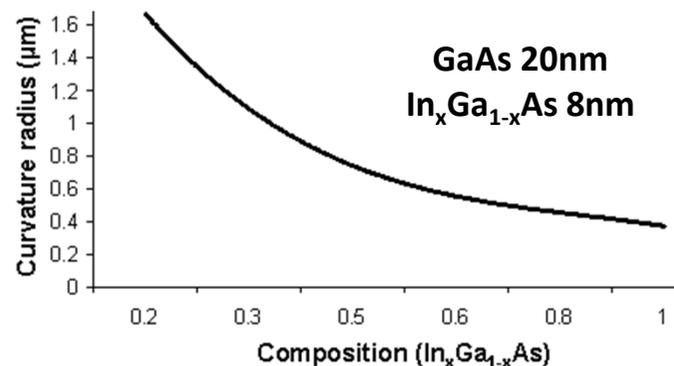
strain

$$\varepsilon = [(a_2 - a_1) / a_1]$$

Curvature radius (macroscopic model)

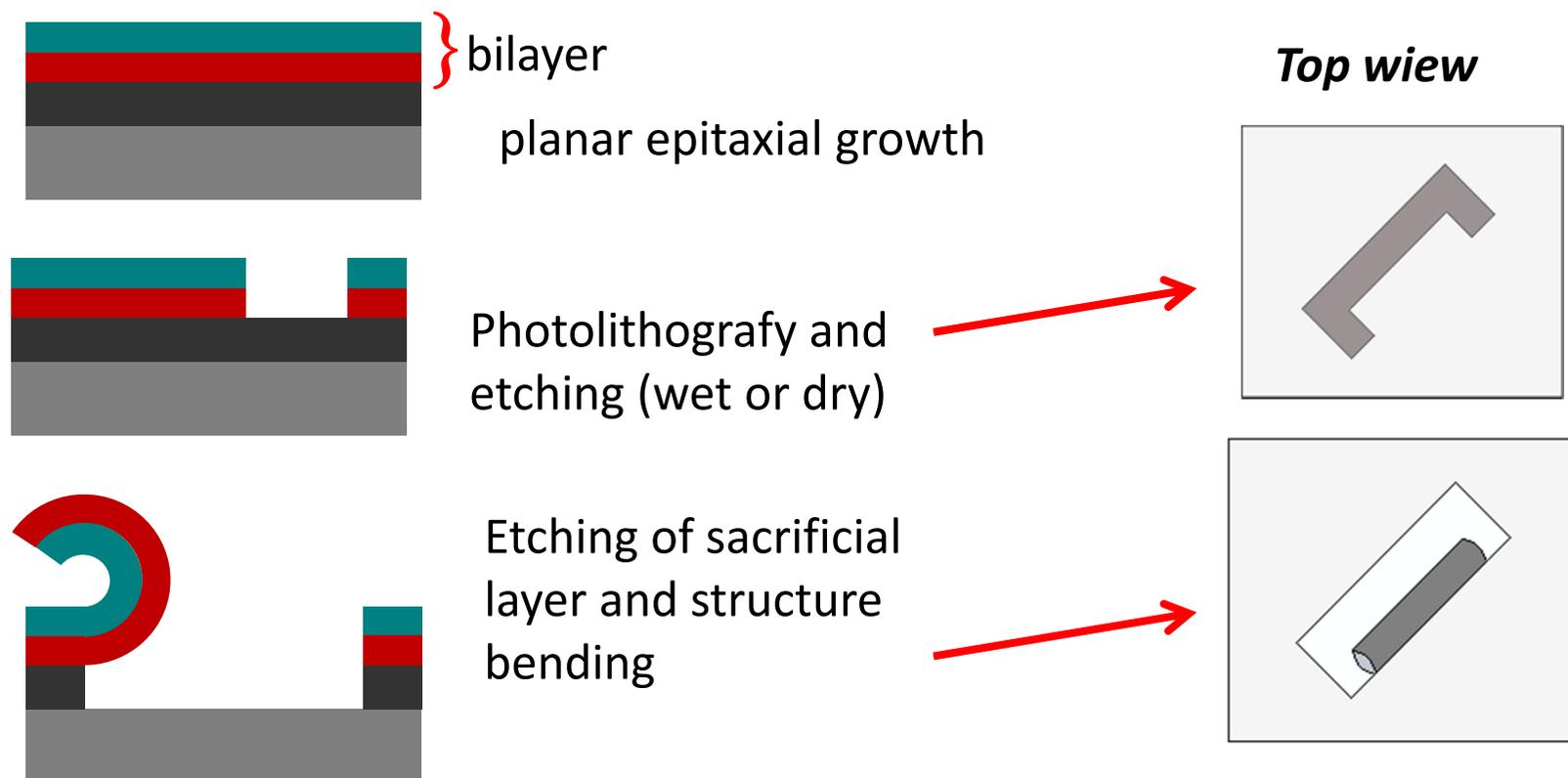
$$R = \frac{d\{3(1+m)^2 + (1+m*n)[m^2 + (m*n)-1]\}}{6\varepsilon(1+m)^2}$$

$d = d_1 + d_2$ total thickness of the bilayer
 $m = d_1 / d_2$ ratio of the two thicknesses
 $n = Y_1 / Y_2$ ratio of the Young's modules



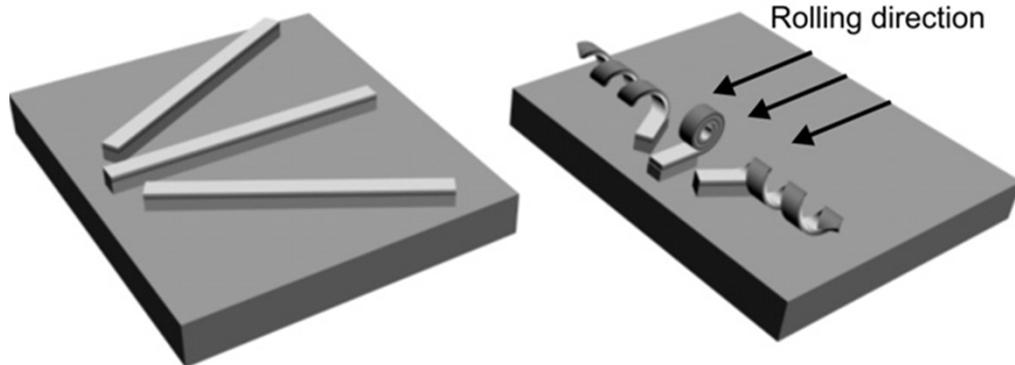
Fabrication

top-down process : **Lithography**
 controls dimension and position down to nanometer scale

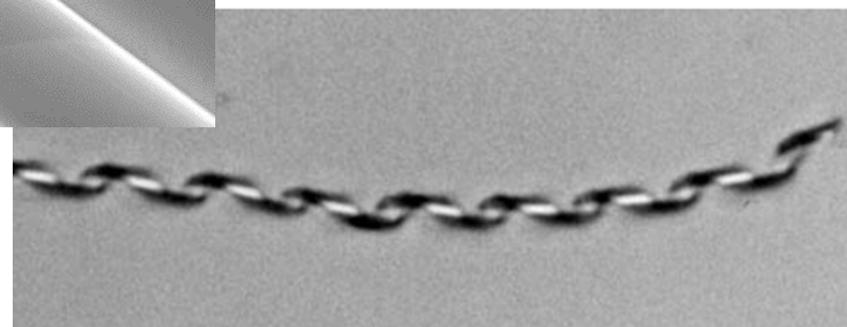
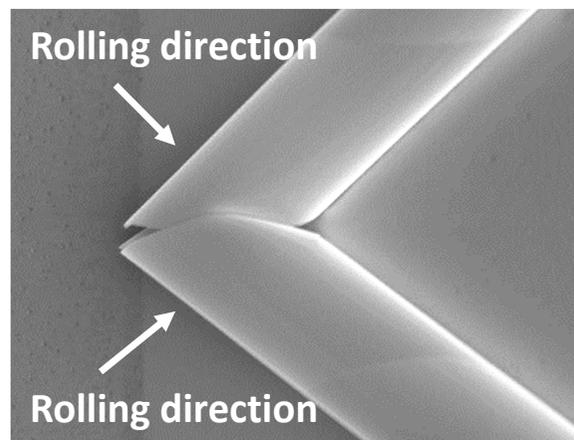
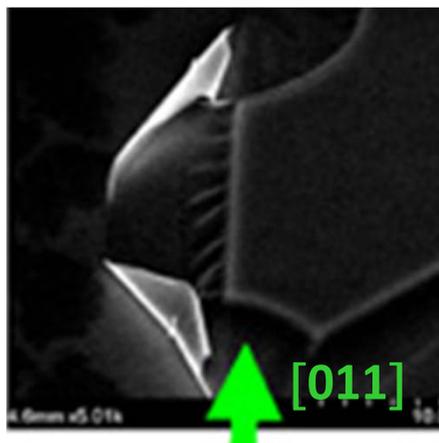


Versatile and simple technique.

Strain anisotropy

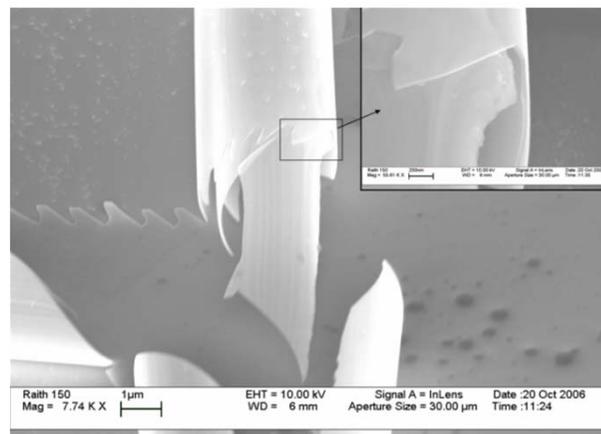
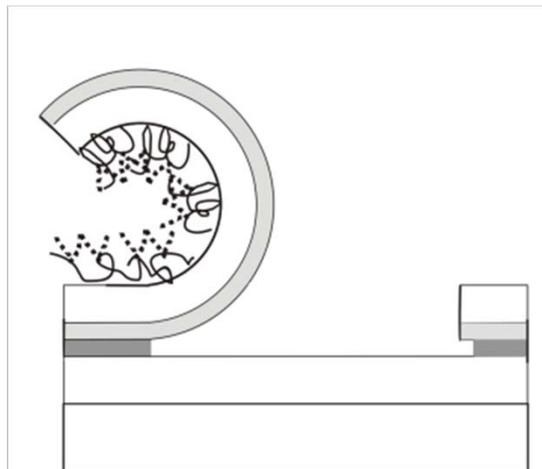


In GaAs Young modul for the [100] direction is 85.3 Gpa and 121.3 GPa for [110]

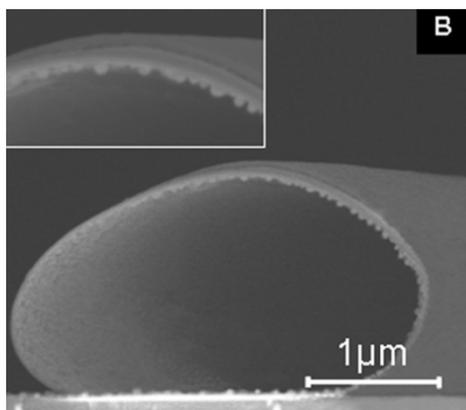


Elaborated shapes are allowed by strain anisotropy

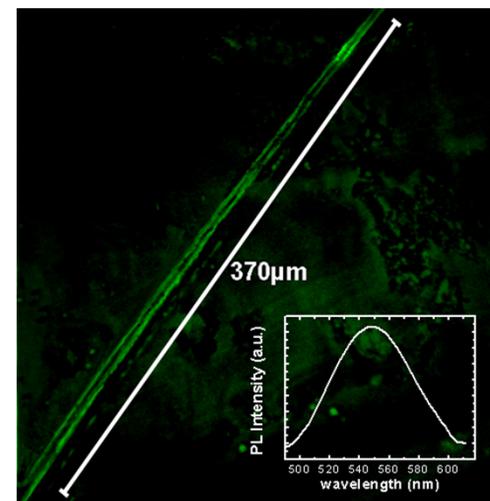
Hybrid microtube



SEM analysis of a broken hybrid microtube



The polymeric template can be infiltrated with polycrystals or dye molecules



The GaAs template can be completely removed

Fluorescence images of functionalized microtubes
 Advances on nanophotonics – 52nd Course-Erice, July 2012

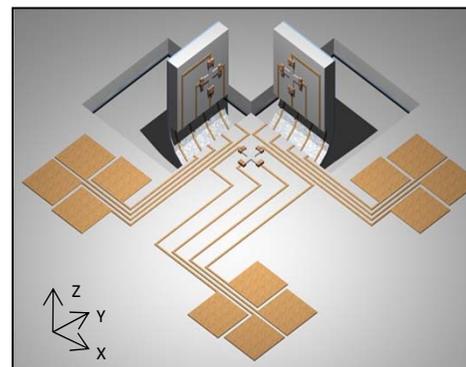
Integrated 3D magnetic sensor



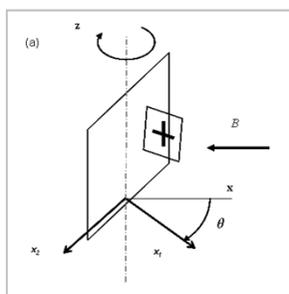
} p-HEMT structure

} bilayer

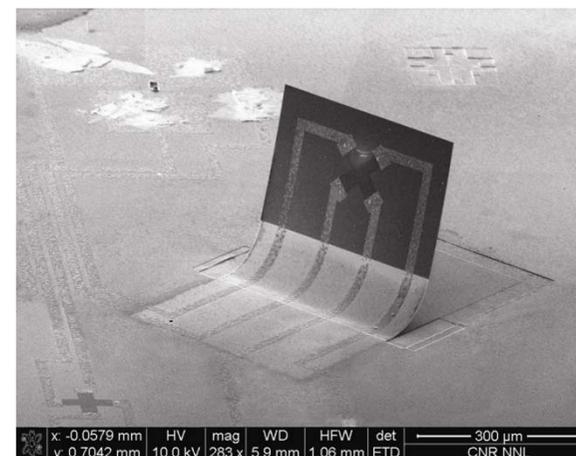
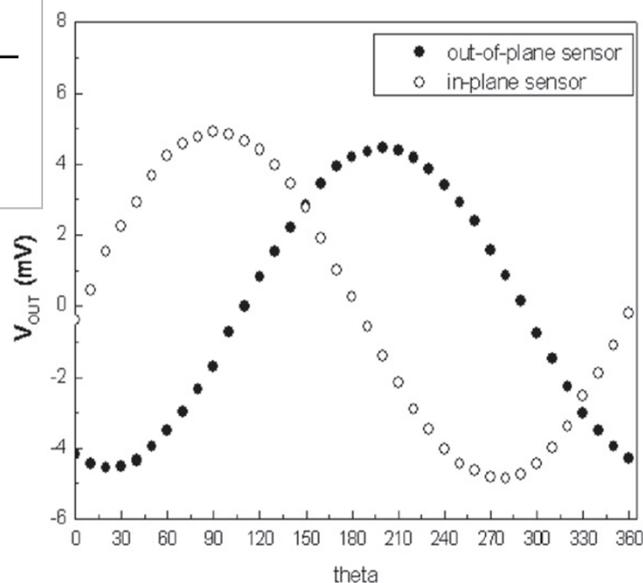
2DEG $\mu \approx 8000 \text{ cm}^2/\text{V}\cdot\text{s}$
 $n = 6.75 \cdot 10^{11} \text{ cm}^{-2}$



Patent "Integrated Triaxial magnetic sensor"
 No: P03246 EP



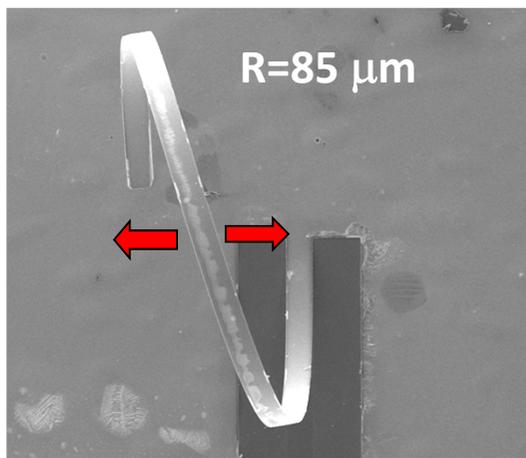
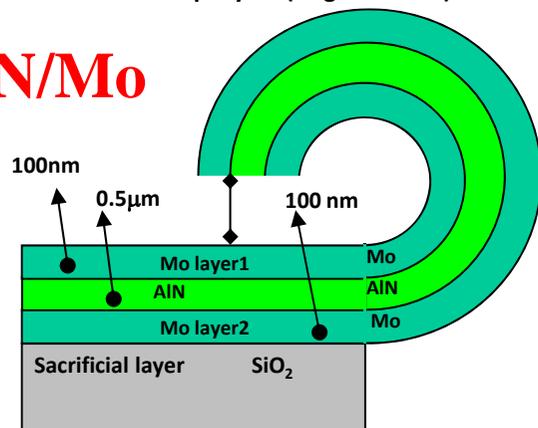
Sensitivity:
 1007 V/AT



Piezoelectric rings for energy harvesting

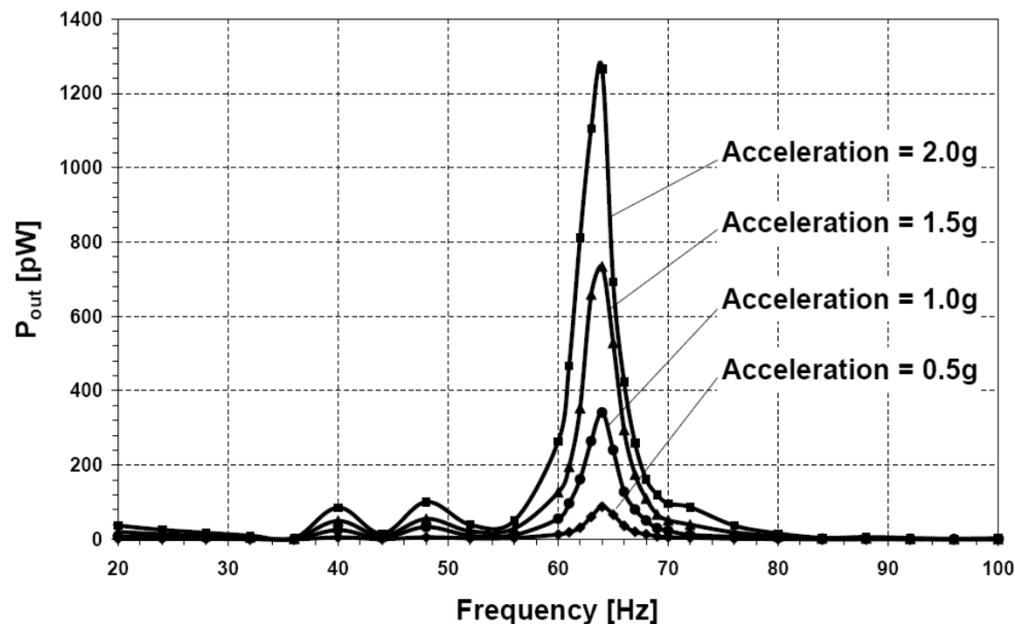
Rolled up layers (ring structure)

AlN/Mo



Power density
 $30.2 \mu\text{W}/\text{mm}^3$

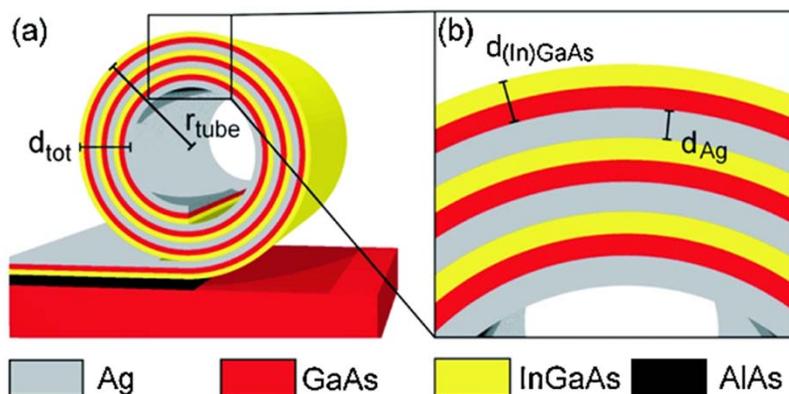
Resonant frequency
64 Hz



microscale dimensions and compatible with CMOS technology

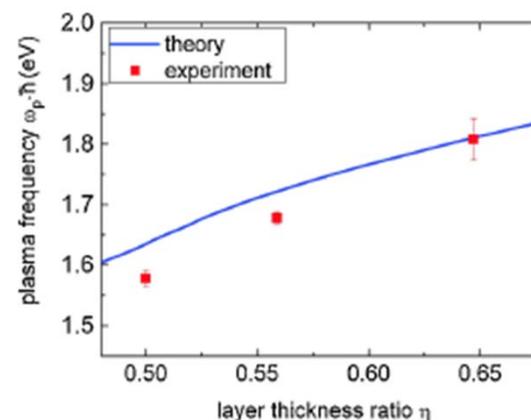
3D structure for metamaterial

Rolled-Up Three-Dimensional Metamaterials with a Tunable Plasma Frequency



Accurately tunable unit cells
and lattice constants

The wall of the tube represents a RSL that consists of alternating layers of metal and semiconductor.

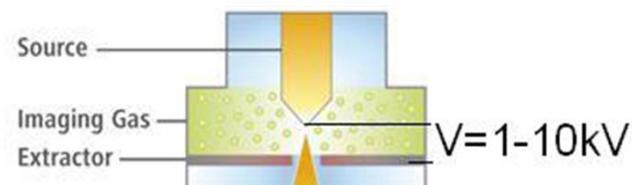
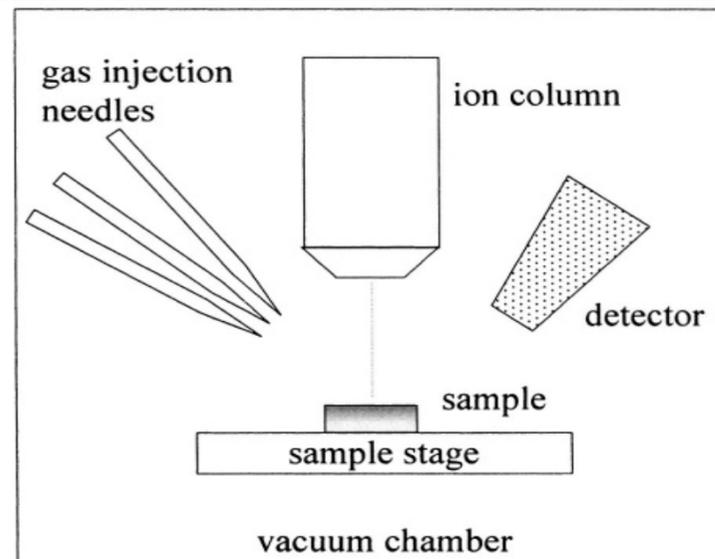


tunable plasma frequency in the visible range

S. Schwaiger et al, PRL 102, 163903 (2009)

- Introduction
- Strategies for Nanofabrication
 - Self assembling method
 - Epitaxial Quantum dot
 - Nanowires
 - Strain driven 3D nanostructures
 - **Ion Beam Induced Deposition (IBID) and nanostructuring**

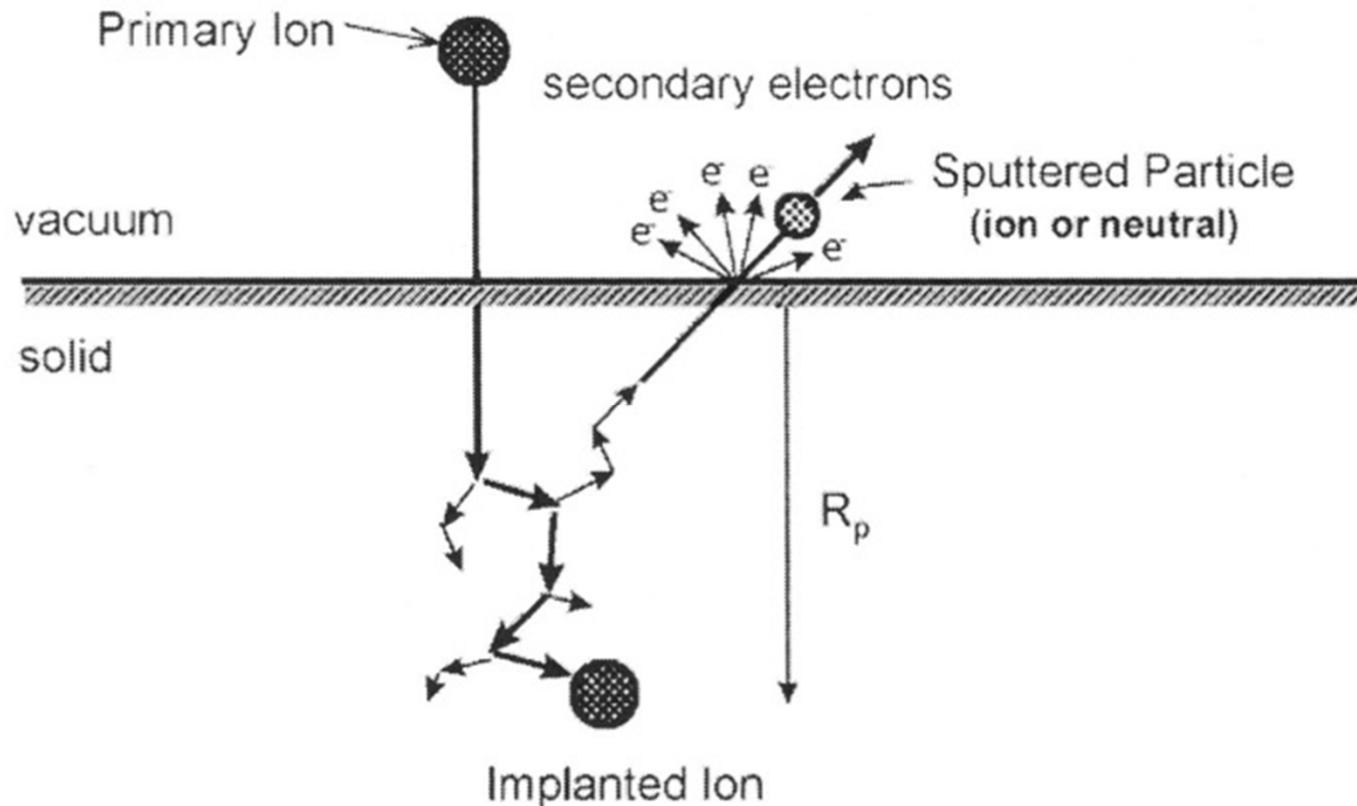
Focused Ion Beam



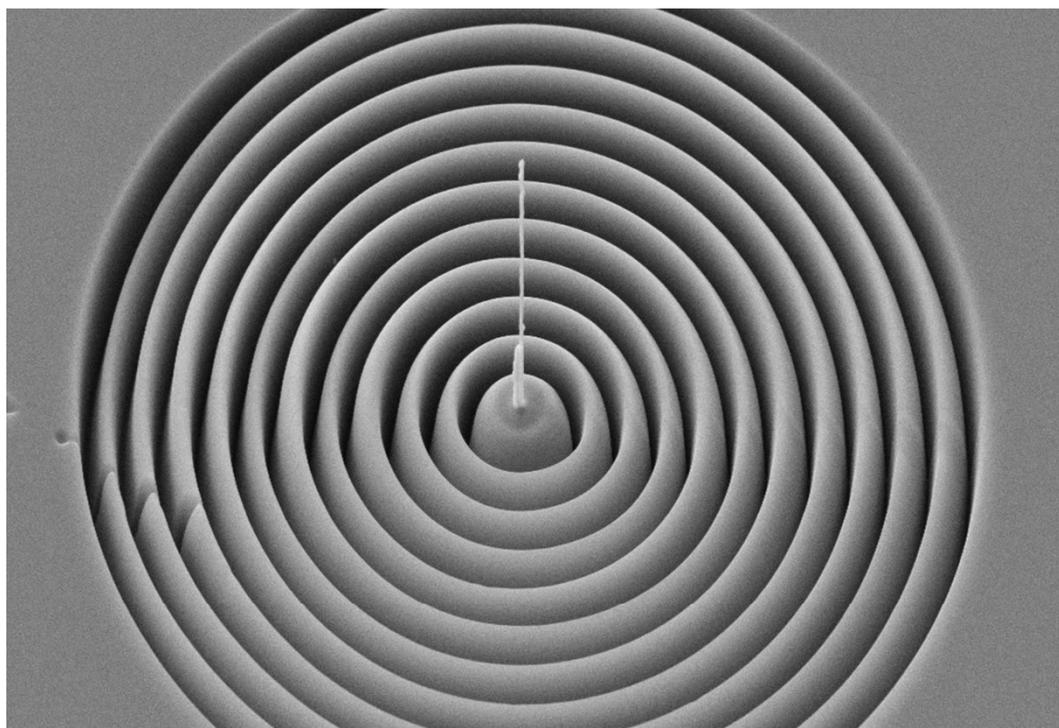
The capabilities of the FIB for small probe sputtering are made possible by the liquid metal ion source (LMIS). The LMIS has the ability to provide a source of ions of ~ 5 nm in diameter.

Ion Milling

Sputtering occurs as the result of a series of elastic collisions where momentum is transferred from the incident ions to the target atoms within a collision cascade region. The kinetic energy must be sufficient to overcome the surface binding energy (SBE) of the target material



Ion Milling

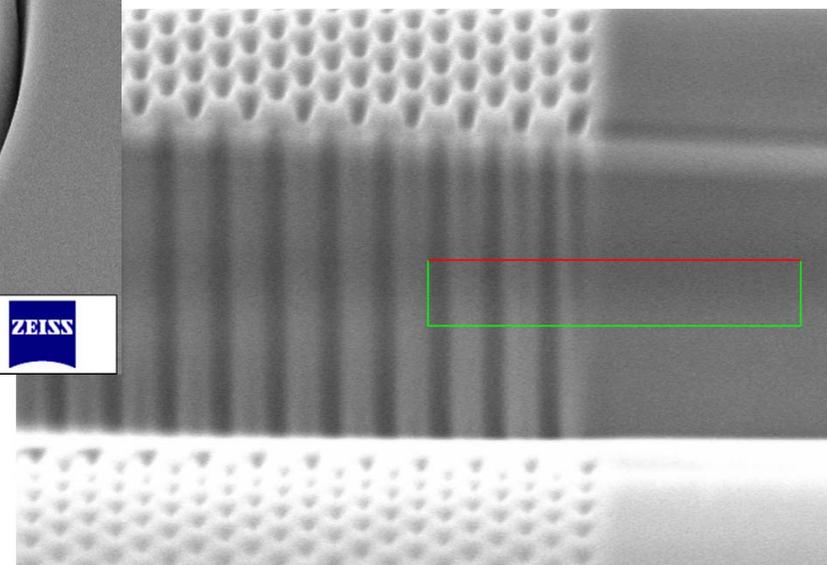


1 μ m

EHT = 5.00 kV

Signal A = SE2

Date :5 Jun 2012



200 nm

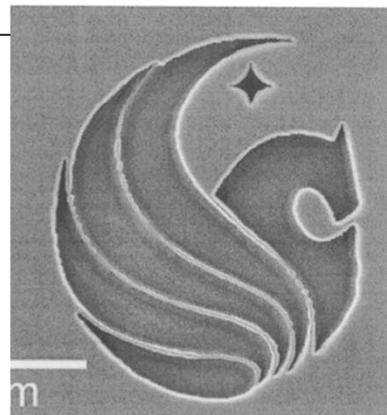
EHT = 5.00 kV

Signal A = SE2

Date :15 Feb 2012

WD = 5.0 mm

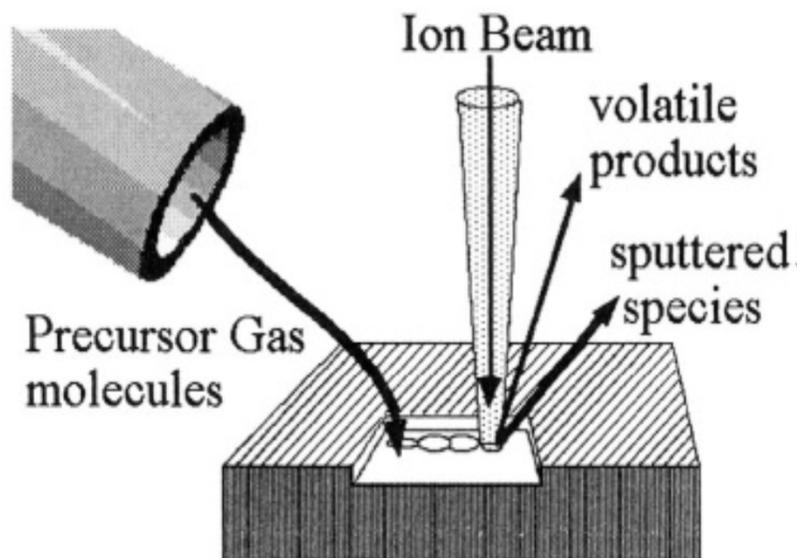
Mag = 19.14 K X



m

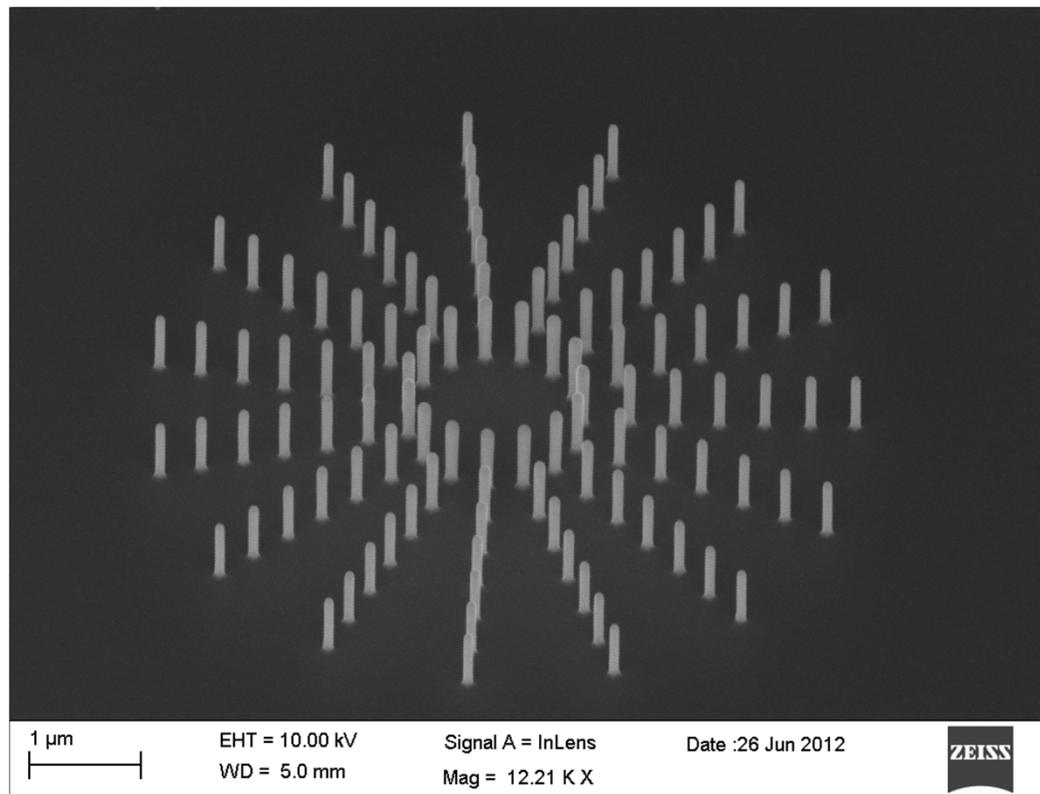
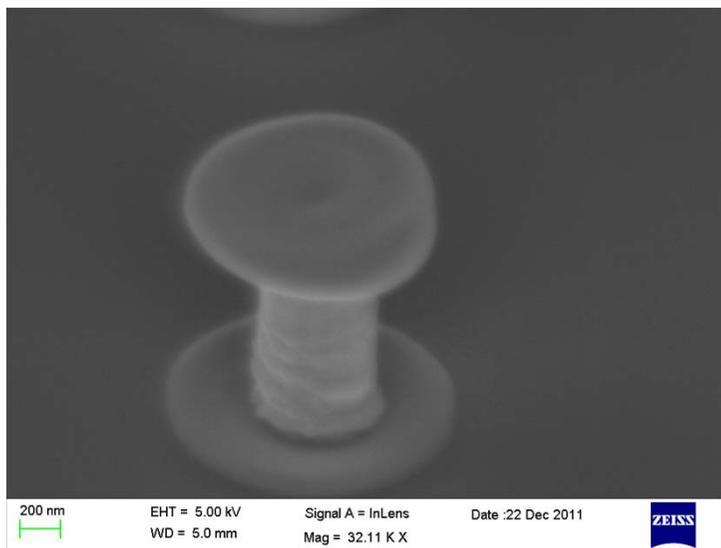
Ion Beam Induced Deposition

Gas delivery systems can be used in conjunction with the ion beam to produce site specific deposition of metals or insulators on almost any solid surface with very high (nanometer) spatial precision



The gas molecules are adsorbed on the surface near the gas inlet, but decompose only where the ion beam strikes

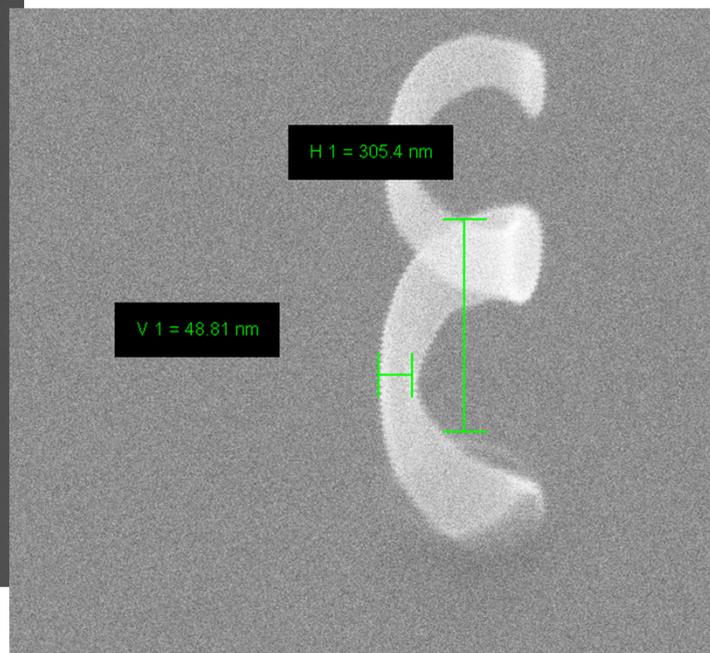
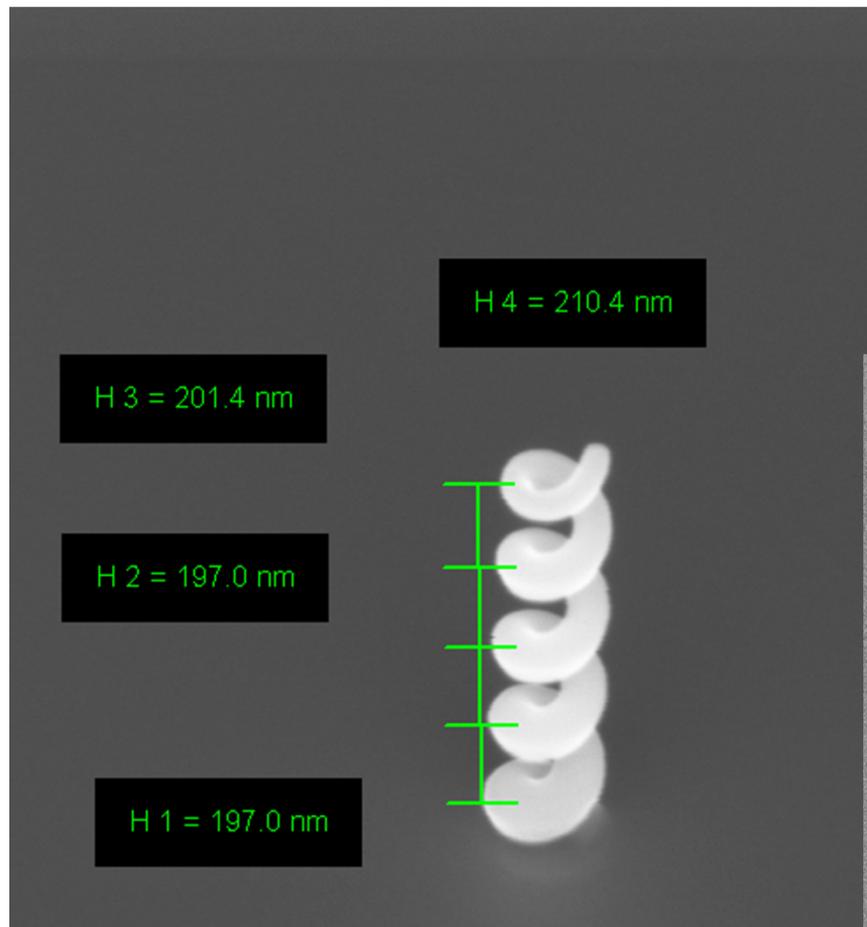
Ion Beam Induced Deposition



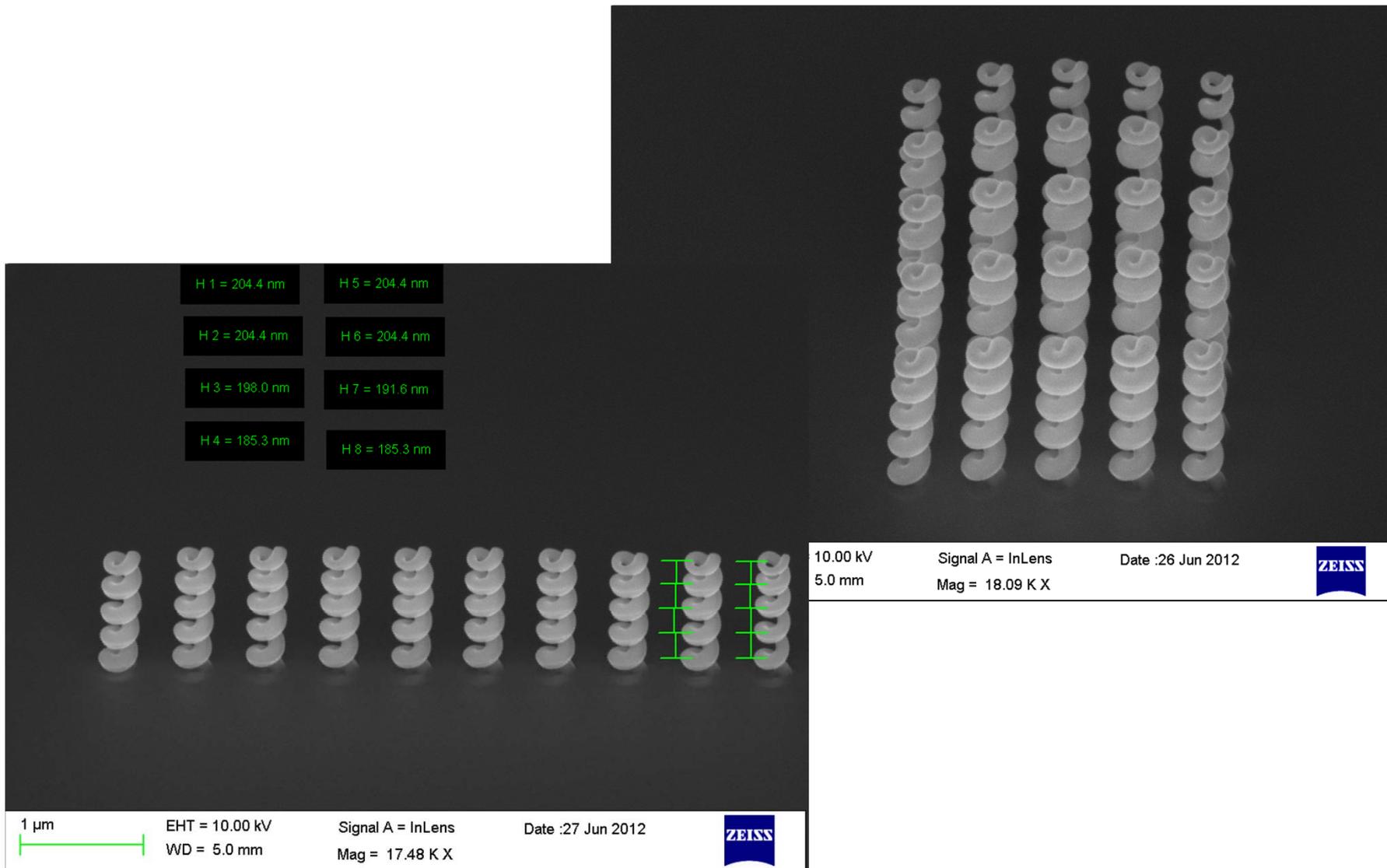
Ion Beam Induced Deposition

Smaller feature with Ion Beam is
around $100 \div 80$ nm

With E-Beam can be lowered to
around $30 \div 40$ nm



Ion Beam Induced Deposition



THANK FOR YOUR ATTENTION